



# The DAMIC-M dark matter experiment

Paolo Privitera

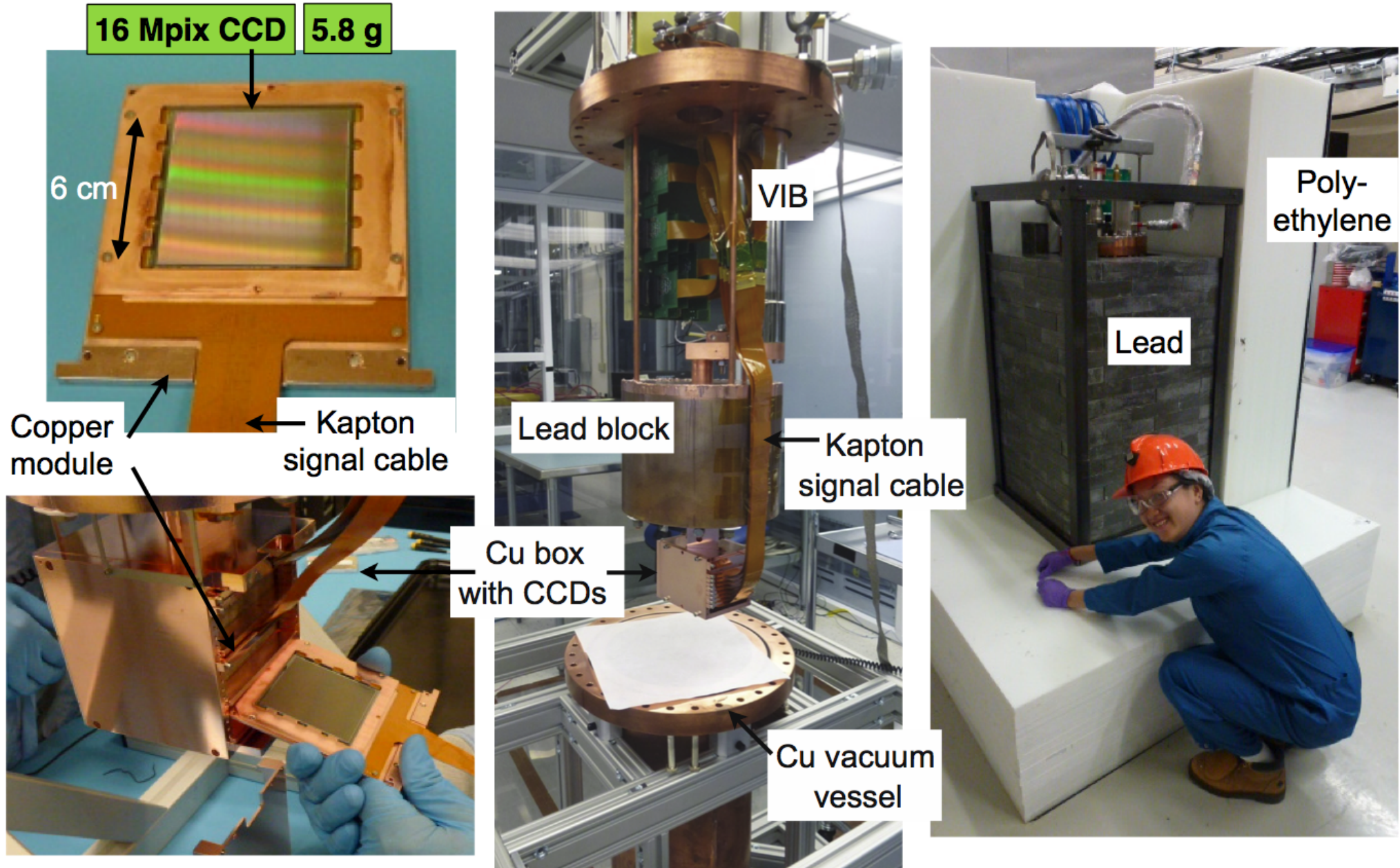


for the DAMIC-M  
Collaboration

(Photo image: particle tracks in a DAMIC CCD )

# DAMIC @ SNOLAB

15  $\mu\text{m}$  x 15  $\mu\text{m}$  pixel, 675  $\mu\text{m}$  thick



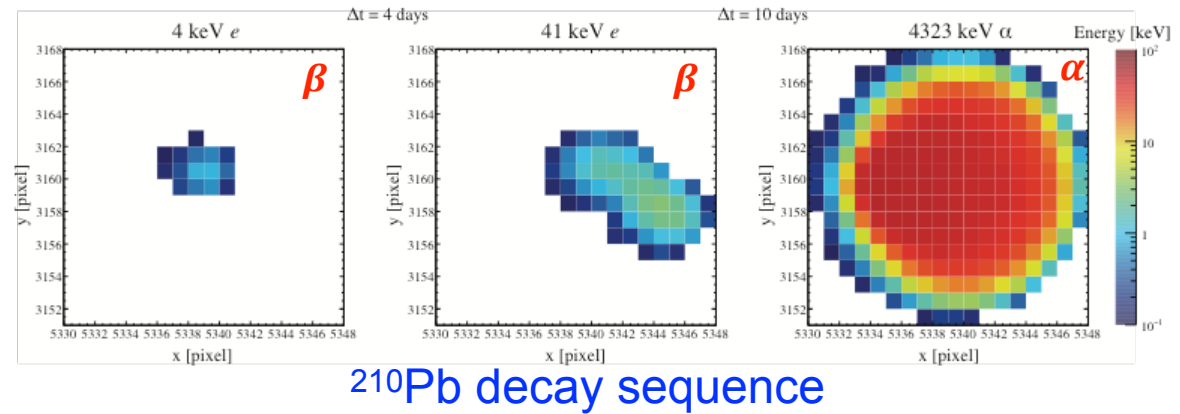
DAMIC-M builds on the experience of DAMIC at SNOLAB

A. Chavarria's talk

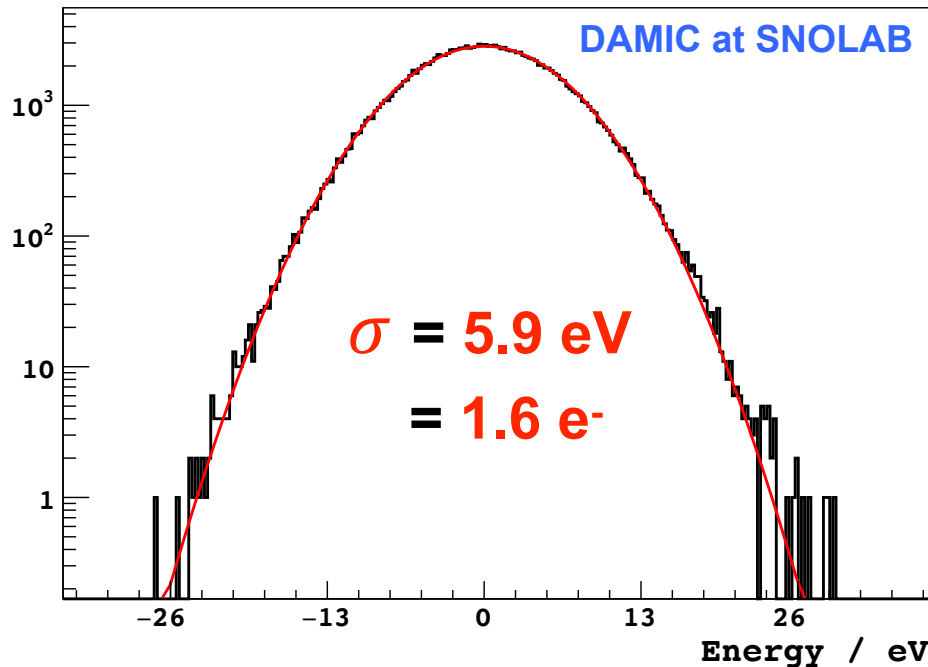
# Dark Matter in CCDs

- Exquisite spatial resolution: unique background characterization and rejection

D. Baxter's talk



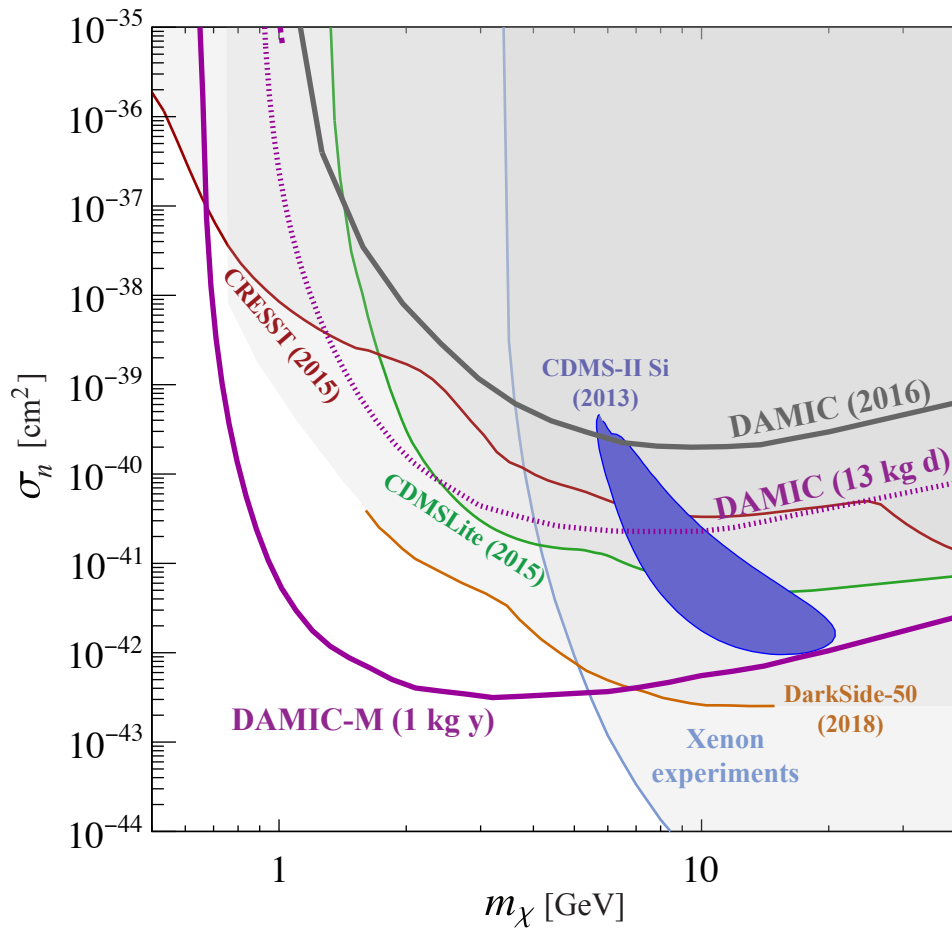
- Extremely low dark current ( $2 \times 10^{-22}$  A  $\text{cm}^{-2}$ ,  $< 0.001$  e/pixel/day)
- Resolution of 2 e- achieved at SNOLAB



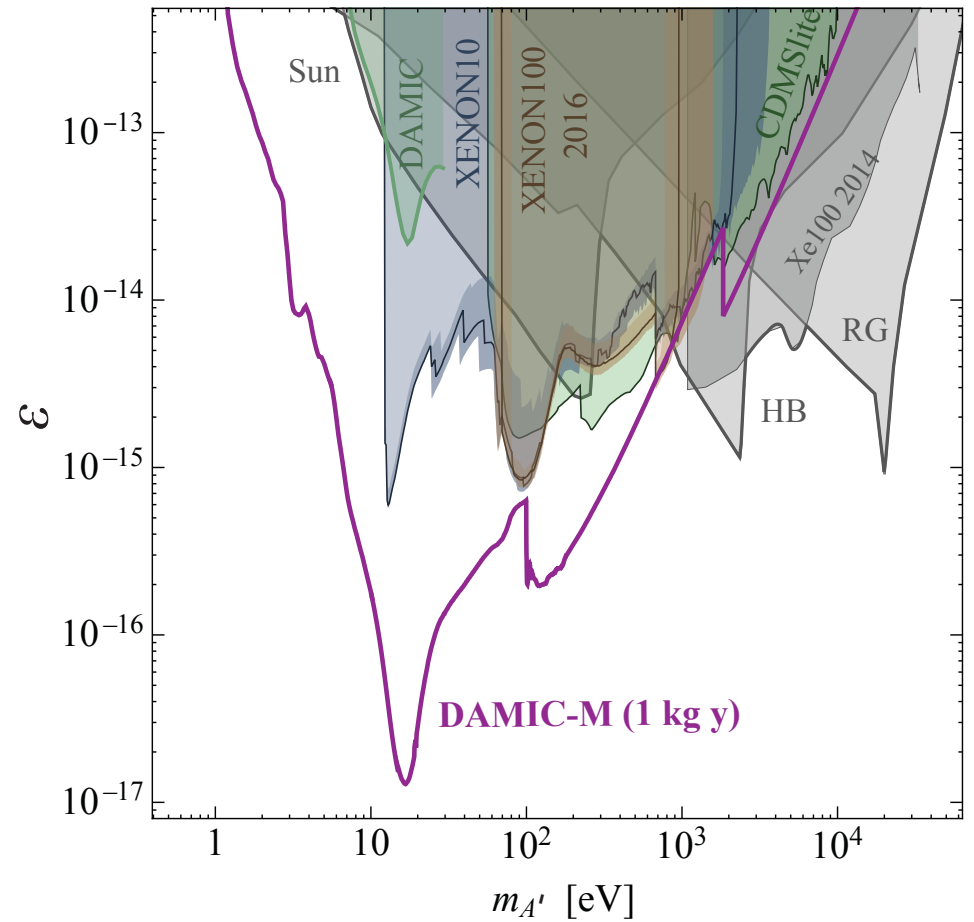
DAMIC-M will feature single electron resolution allowing for detection thresholds of 2-3 e-

# Scientific reach

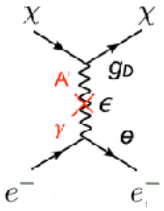
WIMP nuclear recoil search



Hidden photon search



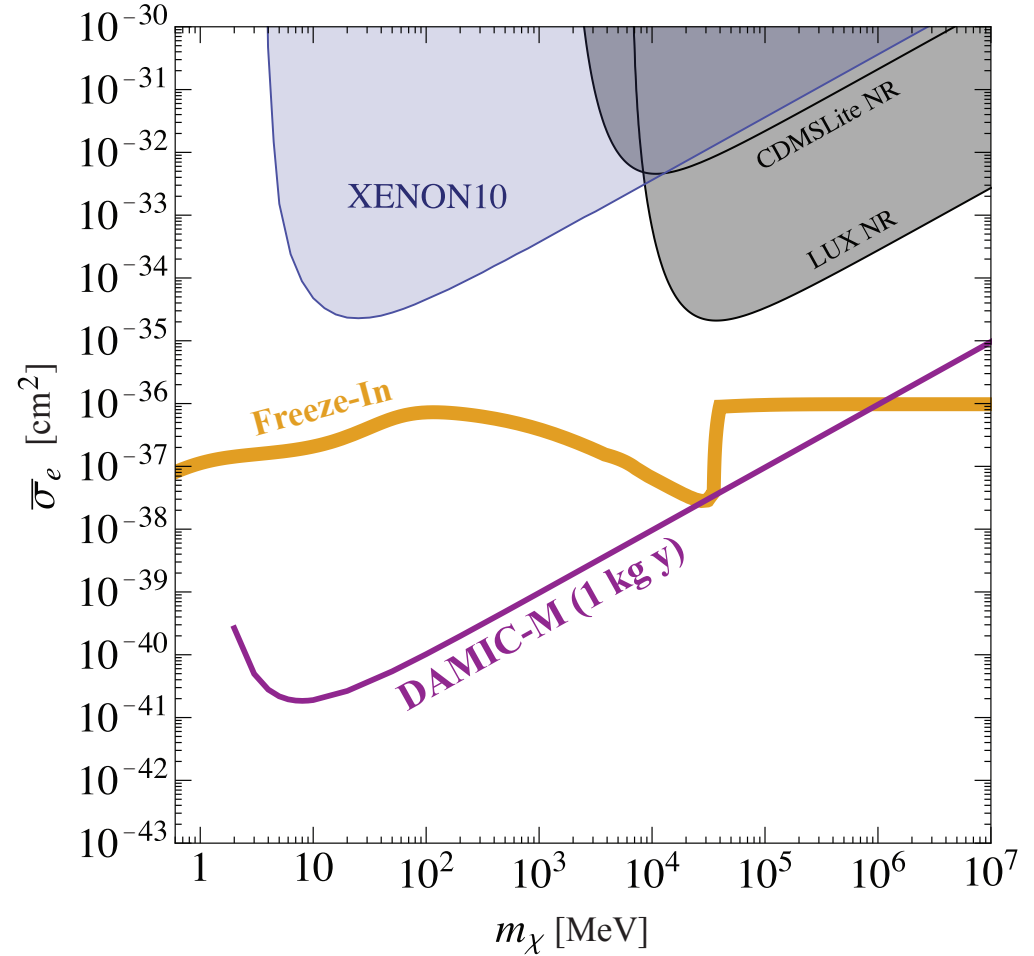
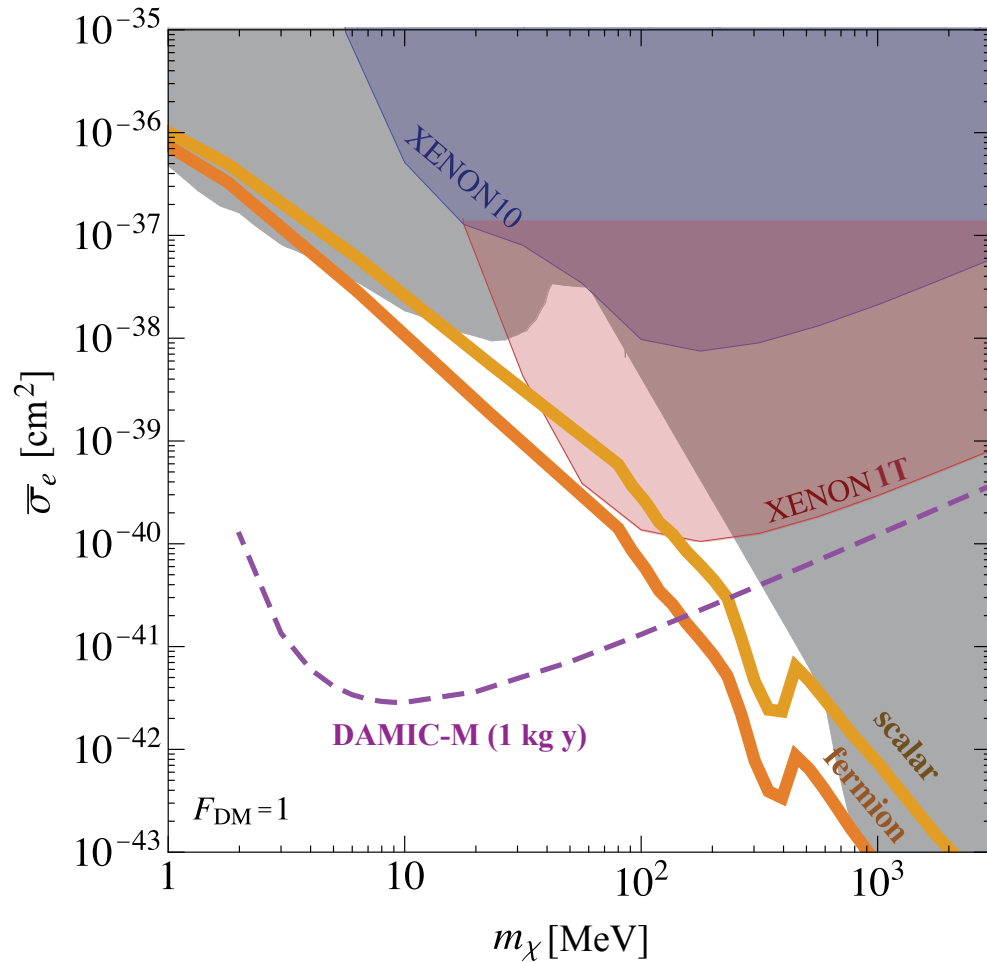
# Scientific reach



Heavy mediator

Light dark matter - electron scattering

Light mediator

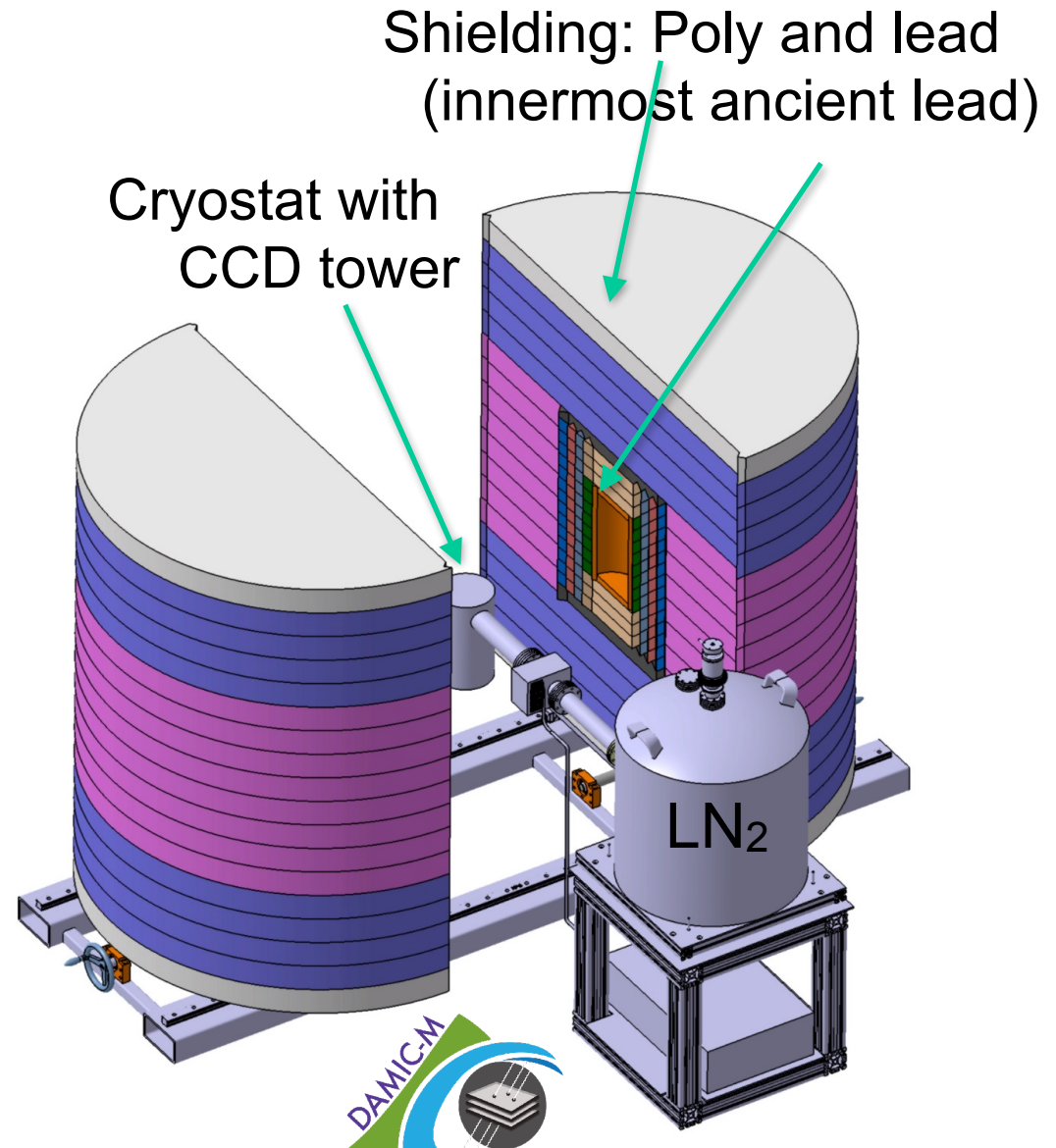


DAMIC-M will be sensitive to light dark matter even if these candidates constitute only a small fraction of the total DM in the universe

# DAMIC-M

DAMIC at Laboratoire Souterrain de Modane

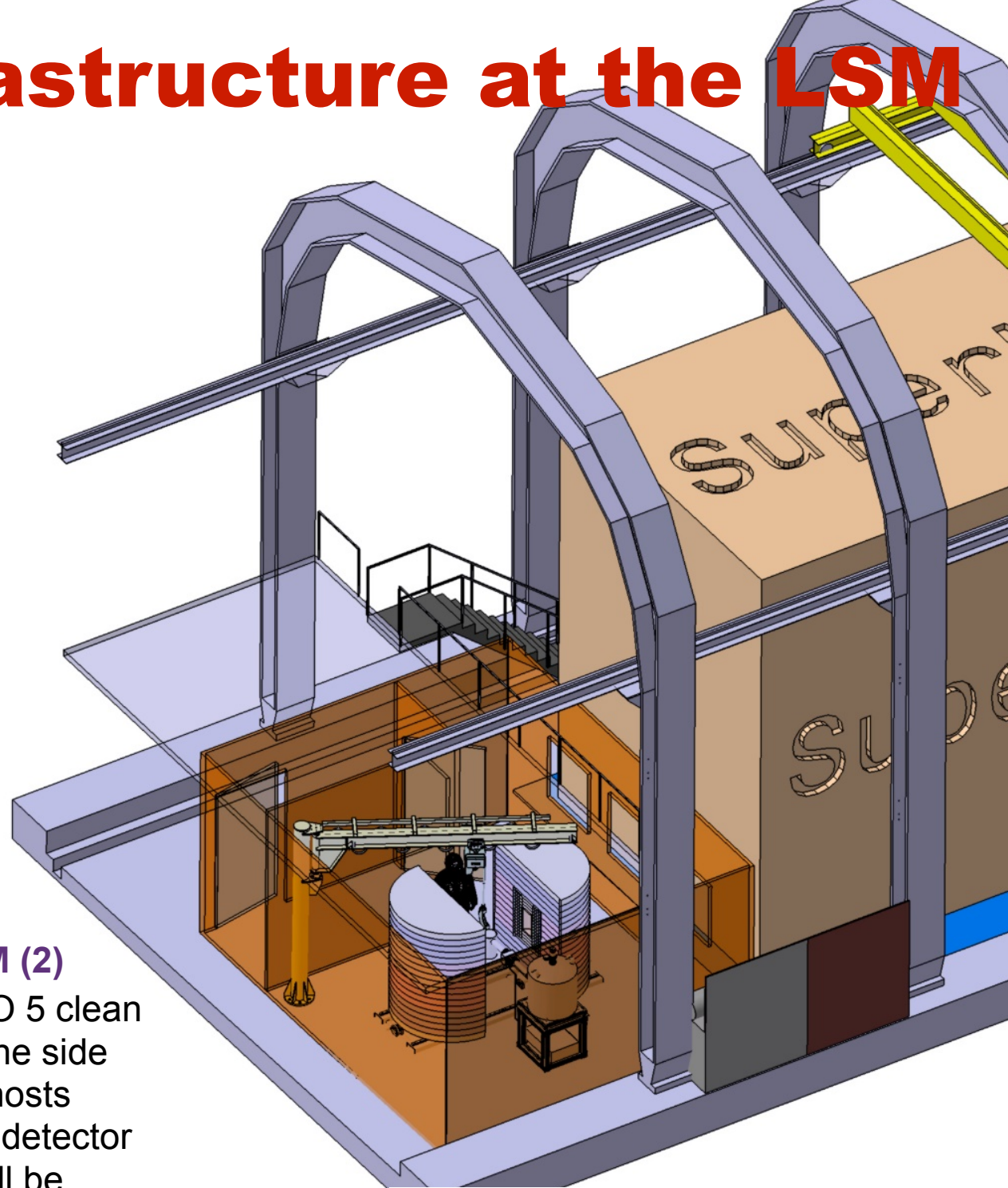
- 50 CCDs (kg-size target mass)
- Most massive CCDs ever built (>10 g each)
- **Single electron resolution** with “skipper” readout (demonstrated by Fermilab SENSEI group)
- A fraction of dru background
- “Classical” design (Ge detectors and DAMIC at SNOLAB)
- R&D and design up to 2021
- Construction 2022
- Installation in 2023



# DAMIC-M infrastructure at the LSM

## DAMIC-M (1)

On the upper floor an ISO 5, radon-free clean room will host the CCD packaging and test facilities



## DAMIC-M (2)

The detector will be installed in an ISO 5 clean room located on the ground floor on the side of SuperNemo. This space currently hosts NEWS-G tests before shipping of the detector to SNOLAB. DAMIC-M clean room will be installed by the end of 2019

# The journey has begun!

Silicon Ingot production by TOPSIL, Frederikssund, Denmark

1	Date	Time	Time zone	Action	Place
2	21.08.2019	23:00	CEST	Crystal pulling starts	TOPSIL
3	22.8.2019	11:15		Crystal pulling ends	TOPSIL
4	23.8.2019	15:00		Pick up by Borge	Copenhagen
5	24.8.2019	16:15		Rigshospitalet cellar	Copenhagen
6	28.8.2019	10:30		Ingot out of the hospital	Copenhagen
7	28.8.2019	13:00		DSV terminal	
8	30.8.2019	10:25	BST	Pick up by Emma	Immingham
9	30.8.2019	14:00		Ingot in BUGS	Boulby



Now at Boulby, waiting for wafering by Shin-Etsu Handotai Europe (Livingston, Scotland)



(DAMIC at SNOLAB wafers were produced in in China, with ingot and wafers shipped by airplane.

One air flight is equivalent to several months of cosmic ray exposure on surface)



underground at Boulby



temporary storage in a shielded facility

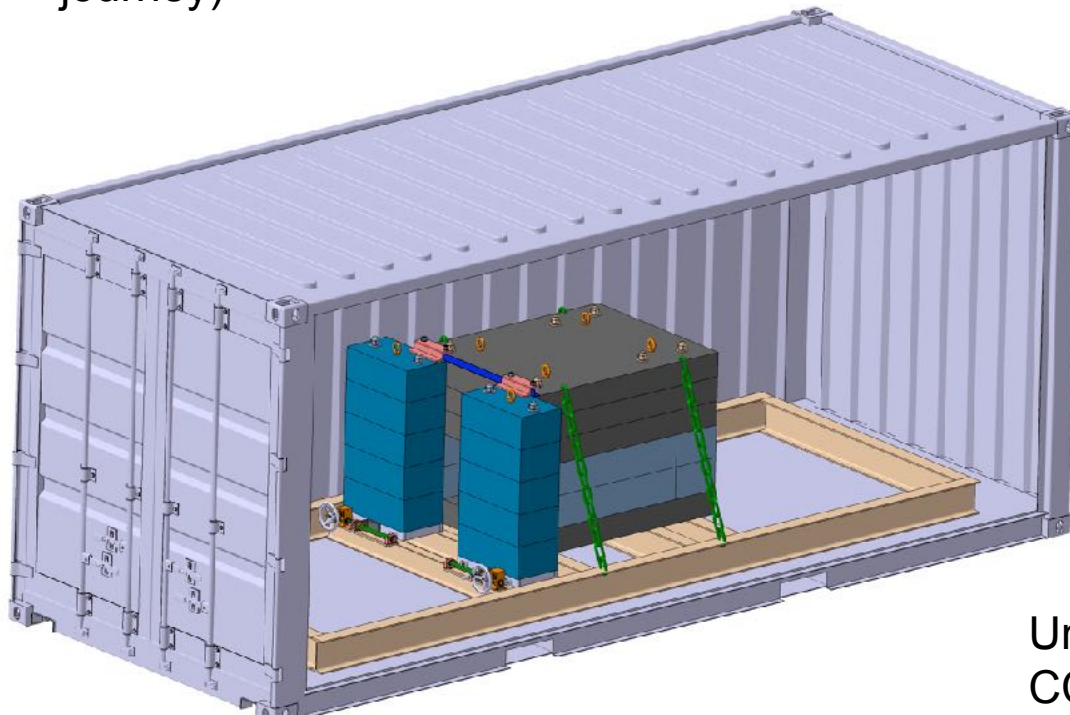
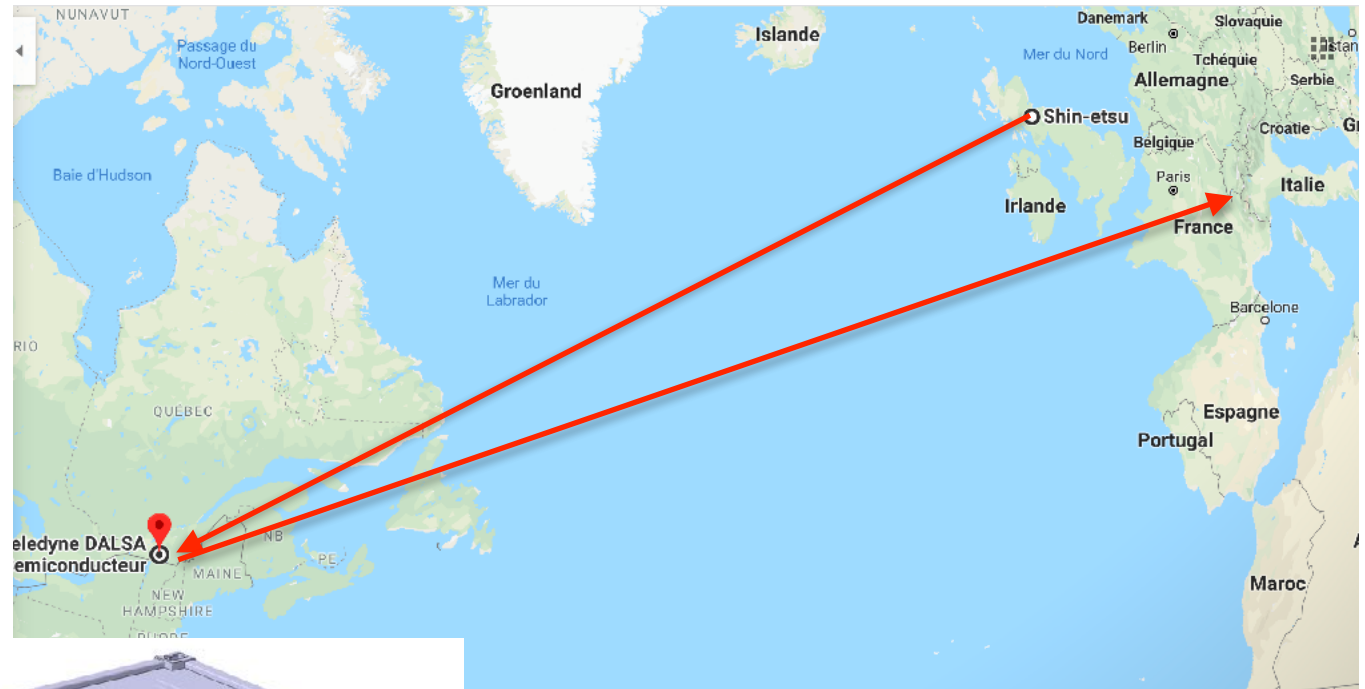


# and will continue!

DAMIC-M CCDs are fabricated by Teledyne DALSA in Canada

The wafers and CCDs will be shipped by sea in a custom-made shielded container

(8-15 days transatlantic journey)



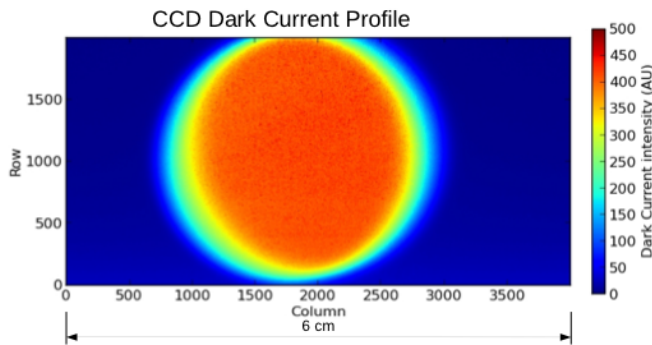
A 20' standard dry container with a  $\approx 15$  t iron shielding. A cavity 50 cm x 40 cm x 110 cm large enough for the CCD packages and the electroformed copper cryostat

The shielding reduces tritium cosmogenic activation by a factor  $\approx 25$

Underground storage at SNOLAB for wafers/ CCDs while in North America

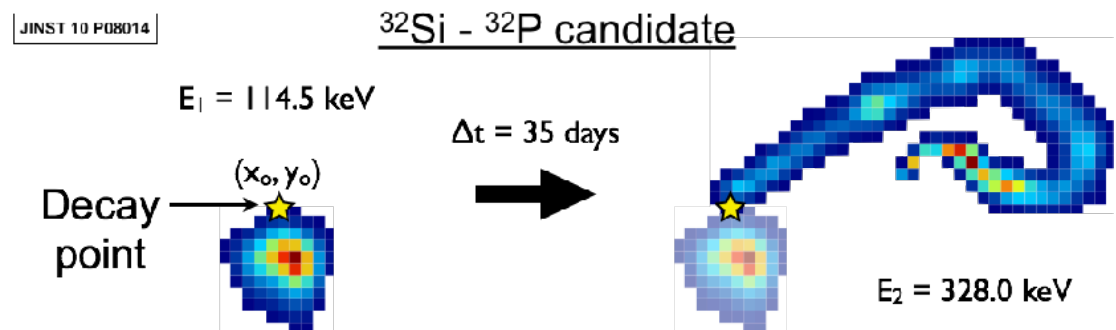
# DAMIC-M Backgrounds

- Most relevant backgrounds identified by DAMIC at SNOLAB **D. Baxter's talk**
- Cosmogenic tritium: minimize exposure to cosmic rays with shielding during transport/fabrication; CCD packaging and test underground at LSM. Also, R&D ongoing to evaluate tritium removal by wafers/CCDs baking.



Activation of a DAMIC CCD at the LANSCE neutron beam. Tritium clearly detected; rate measurement being finalized. **R. Saldanha's talk**

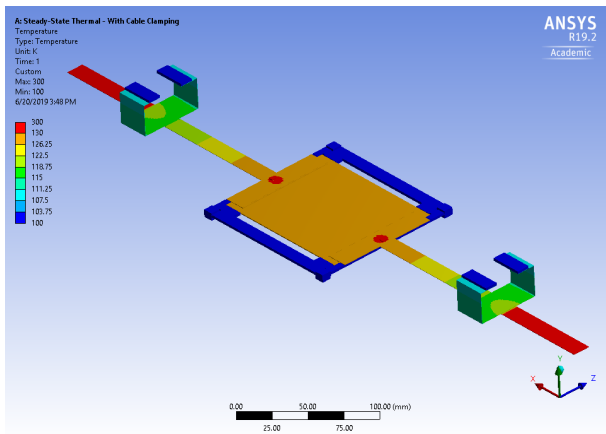
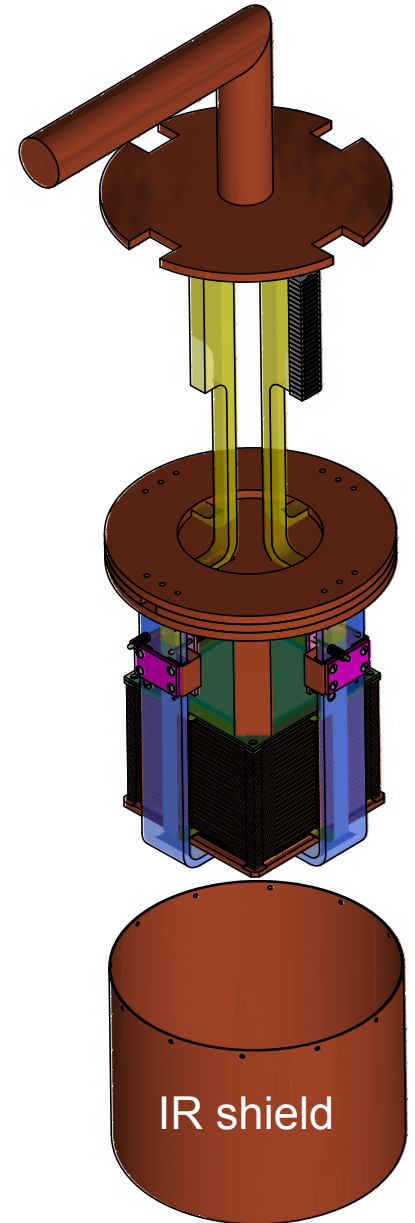
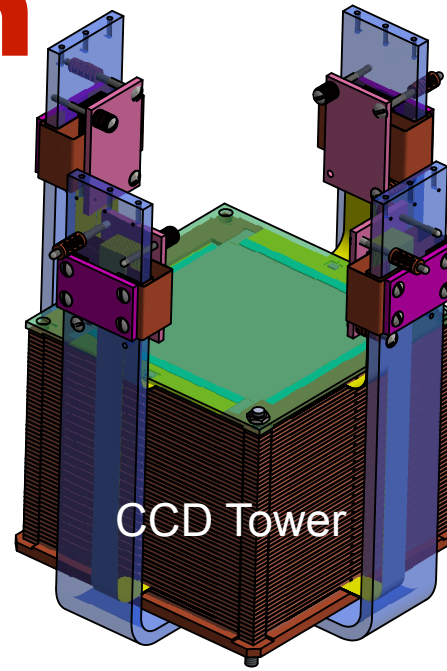
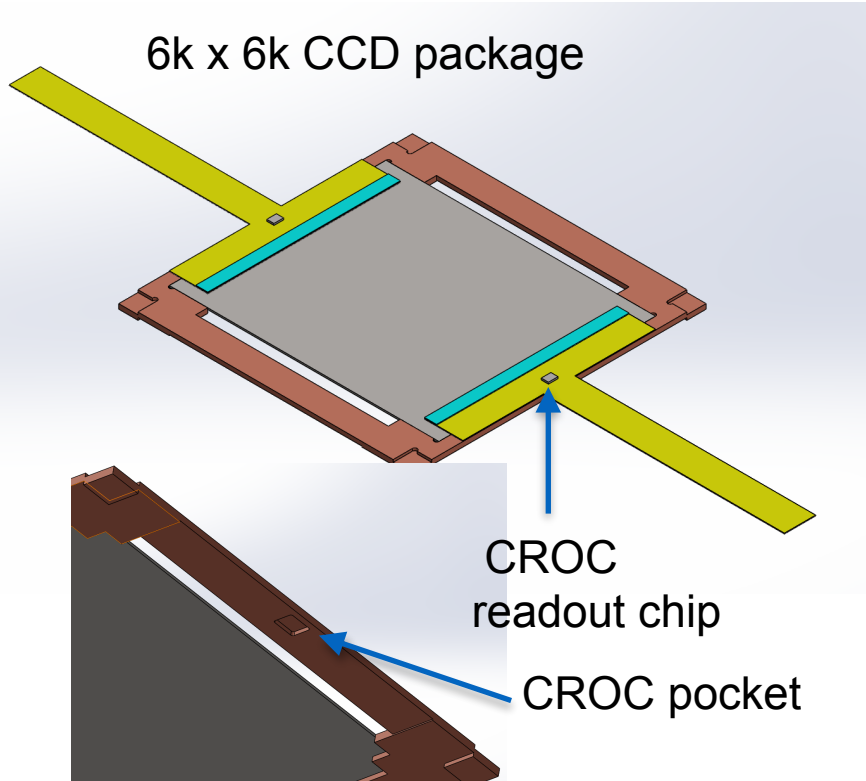
- Cosmogenic  $^{32}\text{Si}$ : spatial correlations



- Surface  $^{210}\text{Pb}$ : minimize exposure to radon (radon-free clean room at LSM for CCD packaging/test; installation in radon-free tent)
- Radiogenic background: material selection and electro formed copper

Challenging goal: 0.1 dru

# Detector Design



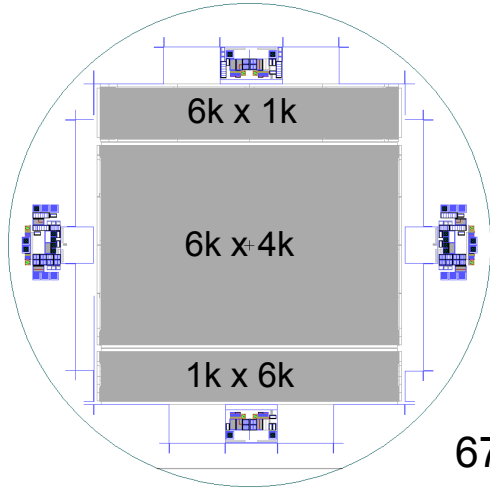
thermal modeling



Design will continue through 2021

# DAMIC-M CCDs

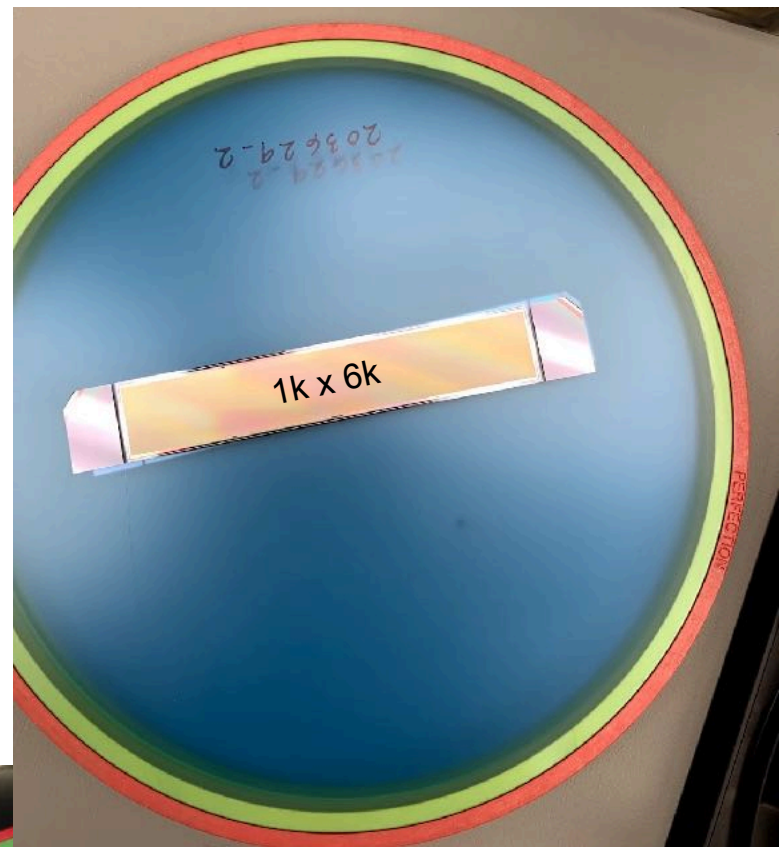
design by S. Holland (LBNL), fabricated by Teledyne/DALSA



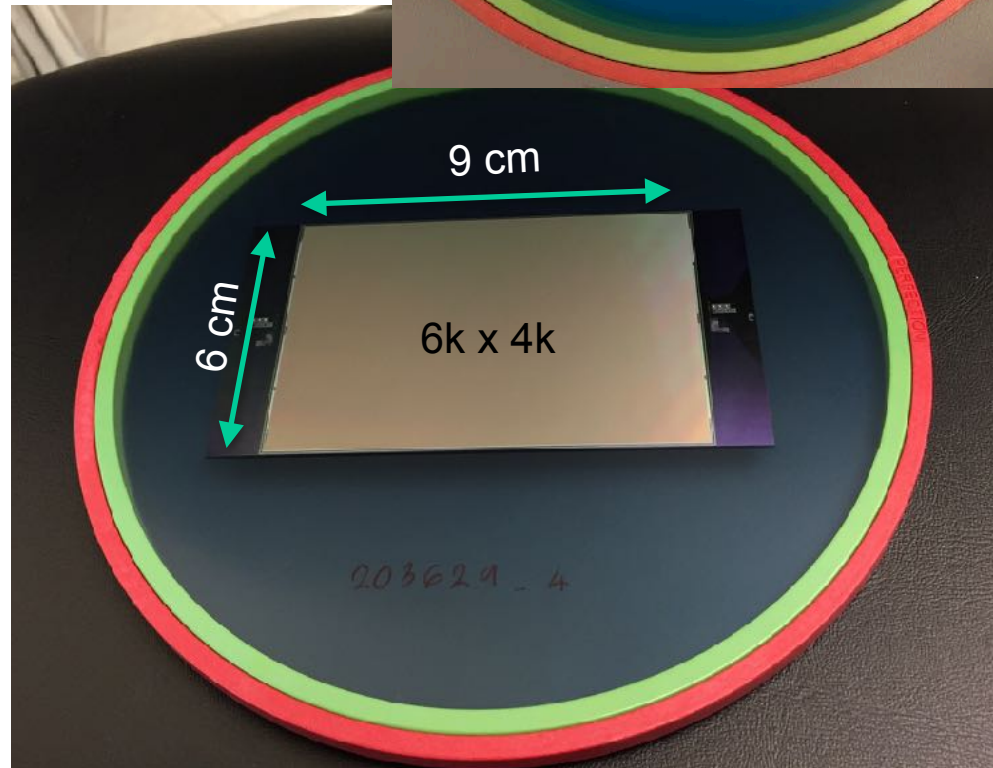
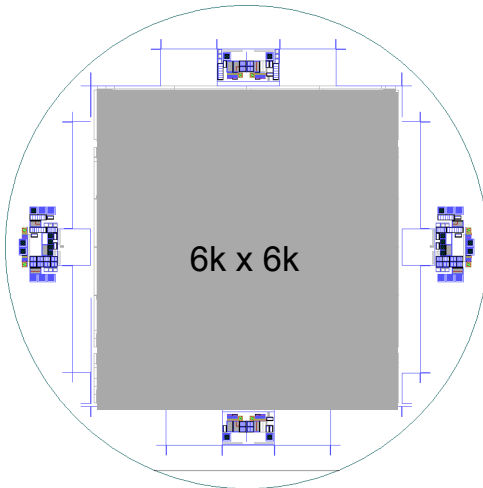
675  $\mu\text{m}$  thick

DAMIC-M prototype skipper CCDs

Three CCDs per 6" wafer to test different skipper readout amplifier design.

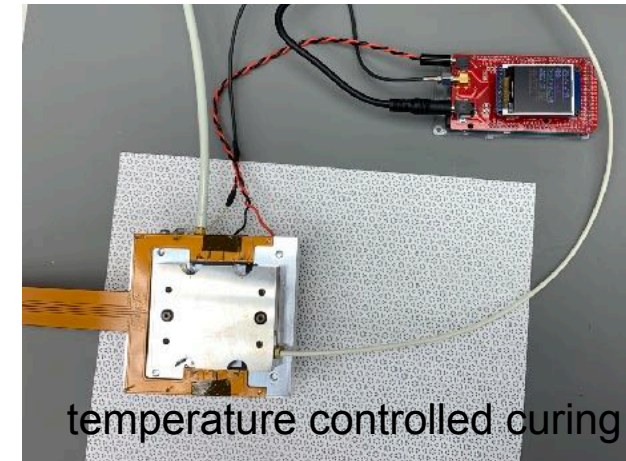
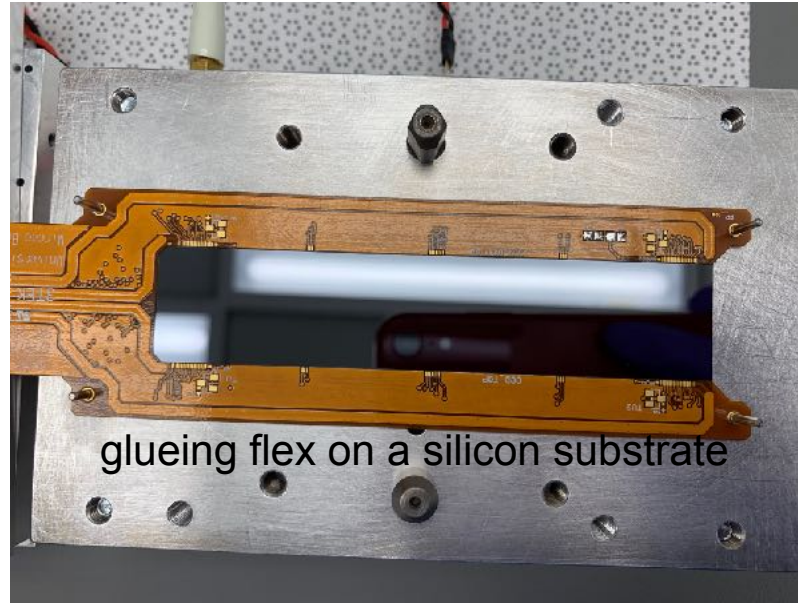


DAMIC-M production skipper CCD design  
9 cm x 9 cm

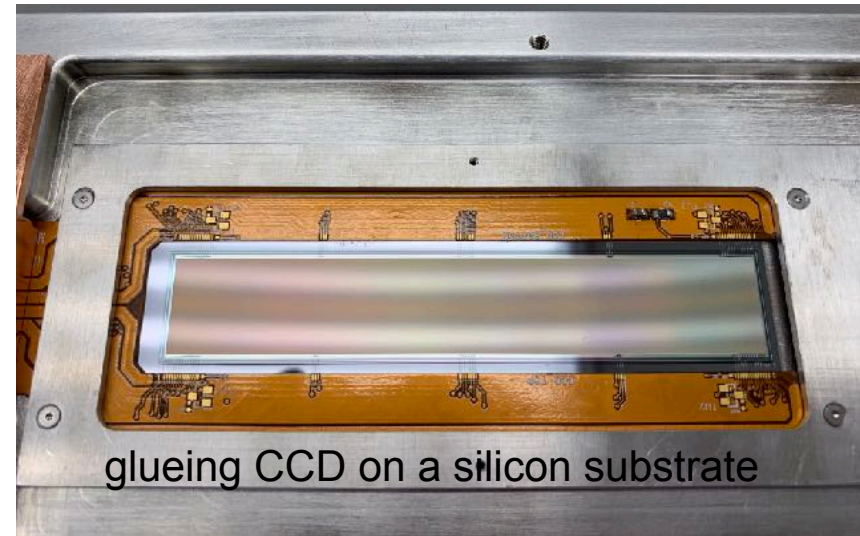
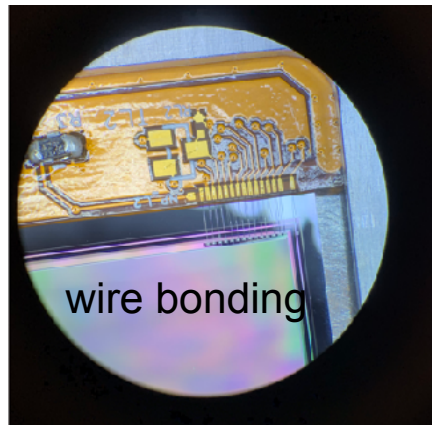


# CCD Packaging

1k x 6k DAMIC-M prototype CCDs

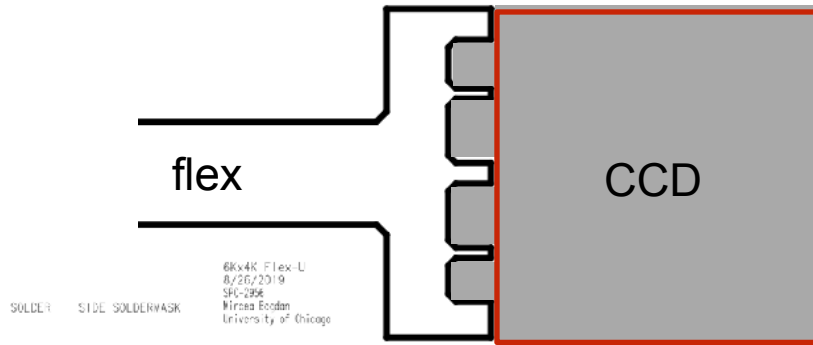


Improvement of packaging procedures originally developed for DAMIC at SNOLAB, notably by reducing the curing (and potential exposure of CCDs to radon) from a day to few hours

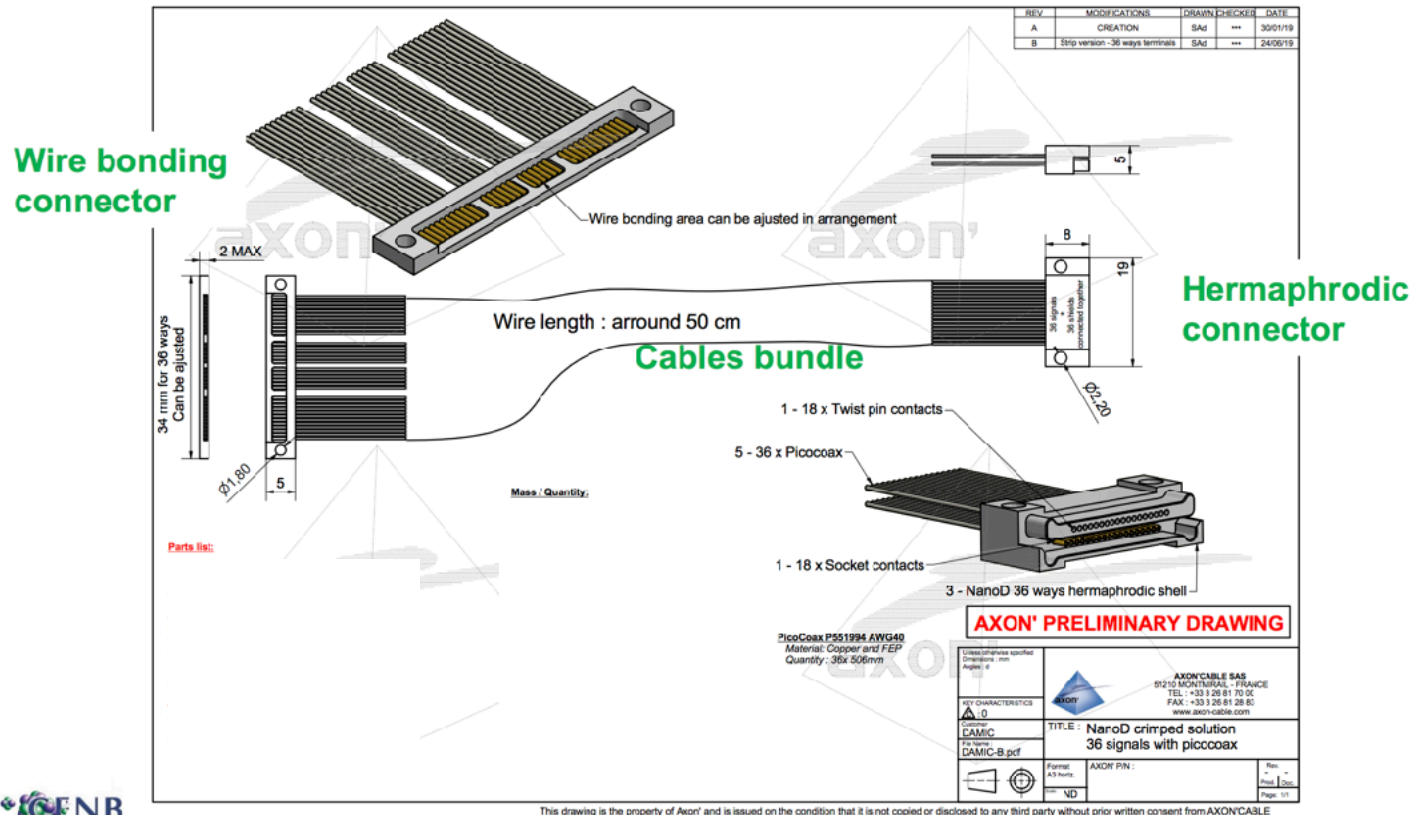


Low background procedures will be implemented for the pre-production and production CCDs (the main objective of the DAMIC-M CCD prototypes is demonstrating single-electron resolution and selection of best skipper amplifiers for the production)

# Low-background cables



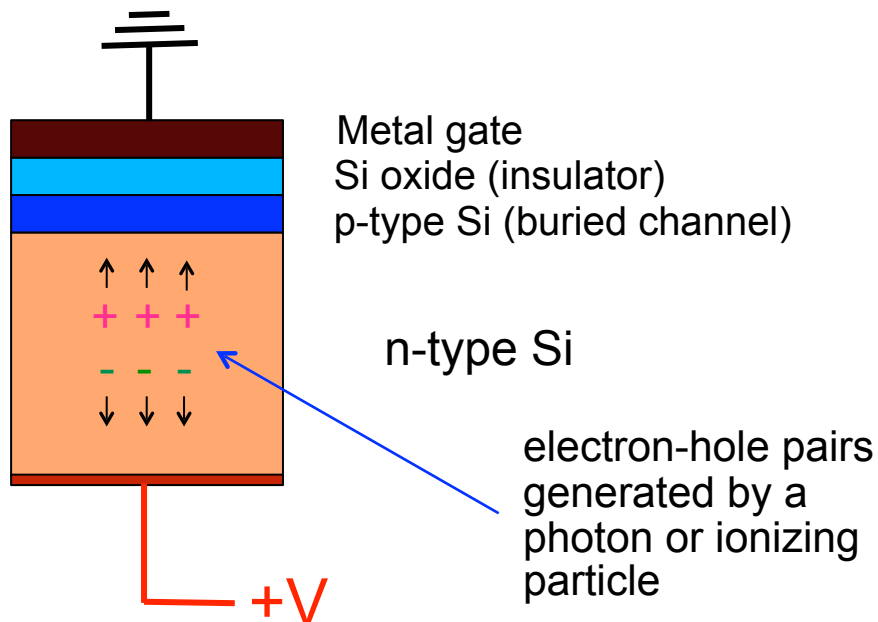
Flex cable R&D:  
 minimize mass close to CCD;  
 develop clean fabrication procedures for multilayer flex (PNNL)



We are also pursuing with AXON a solution employing picocoaxial cables (low-background demonstrated by MAJORANA)

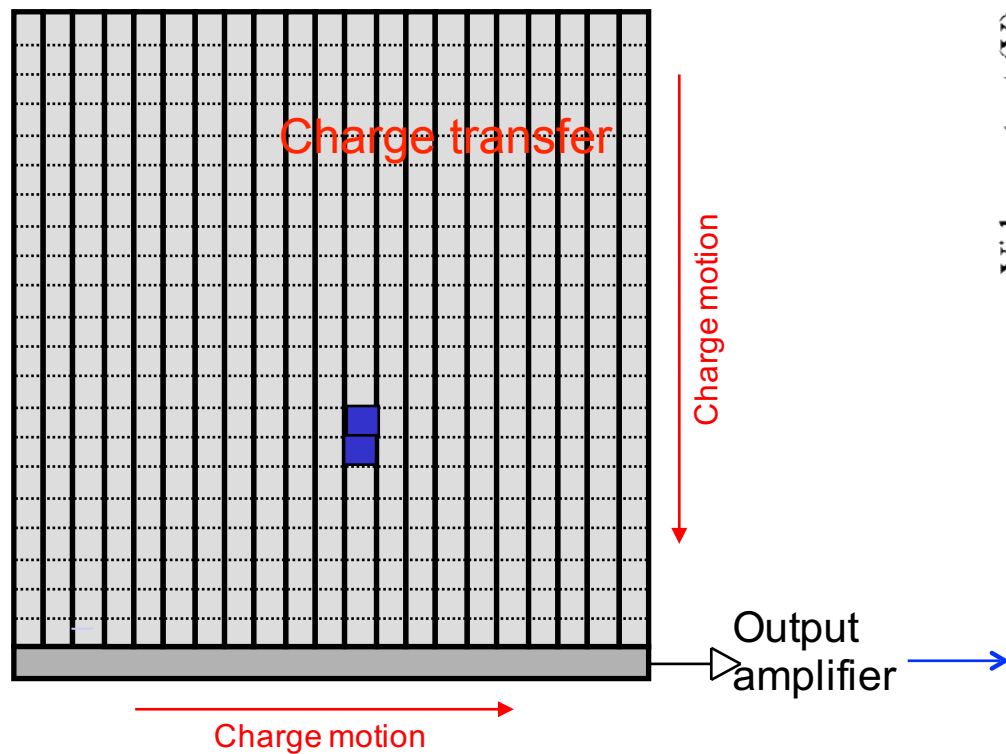
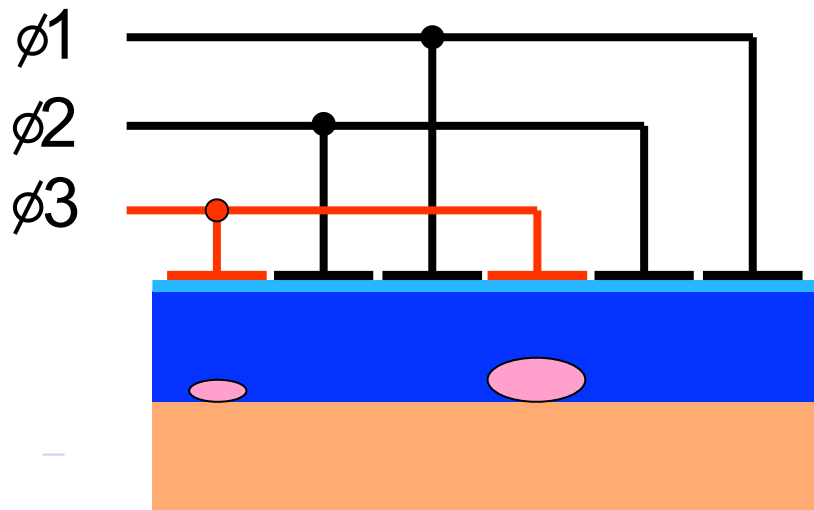
Both would fulfill our requirements for cables' radio purity

# Metal-Oxide-Semiconductor capacitor

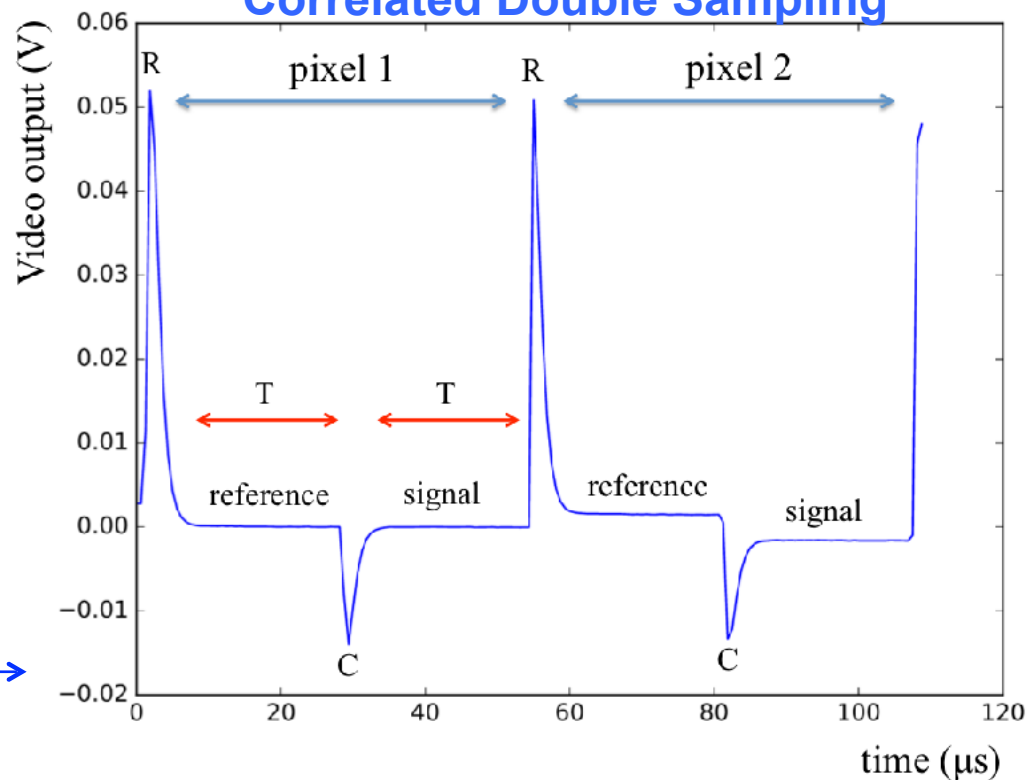


# Charge Coupled Device

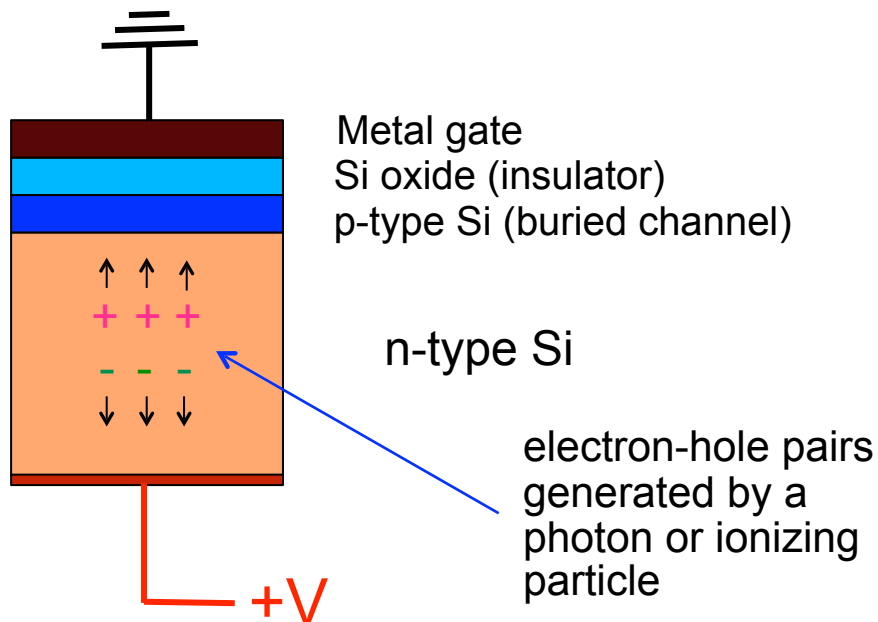
## Charge transfer ("Clocks")



## Correlated Double Sampling

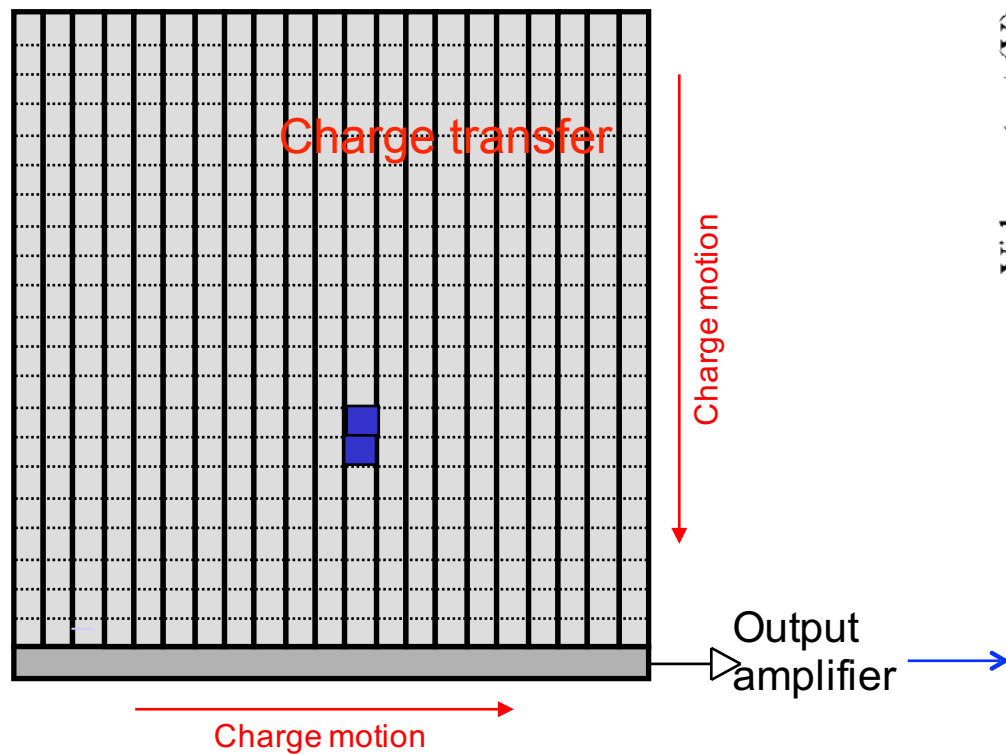
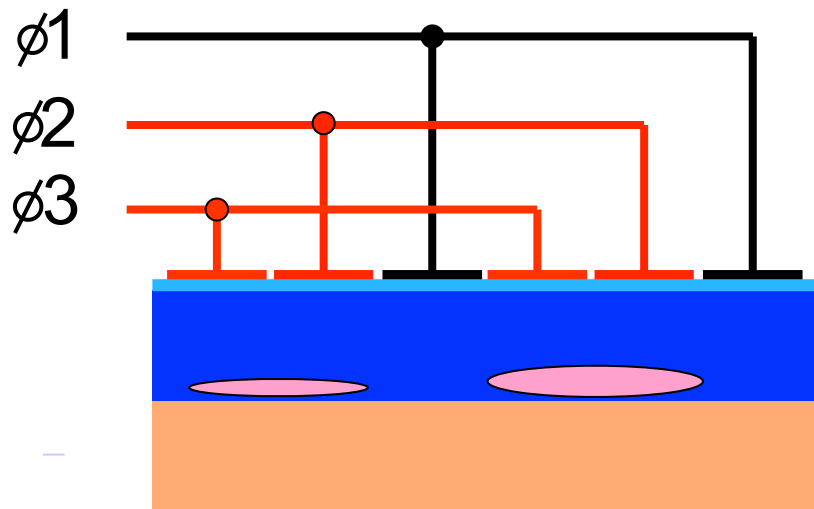


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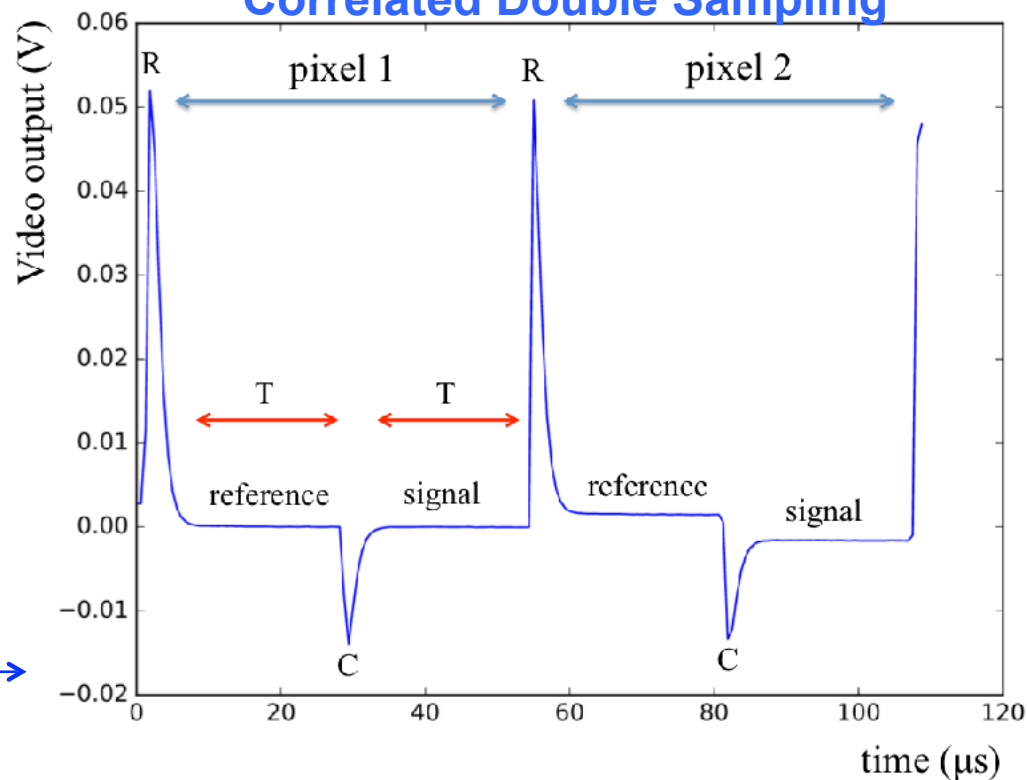


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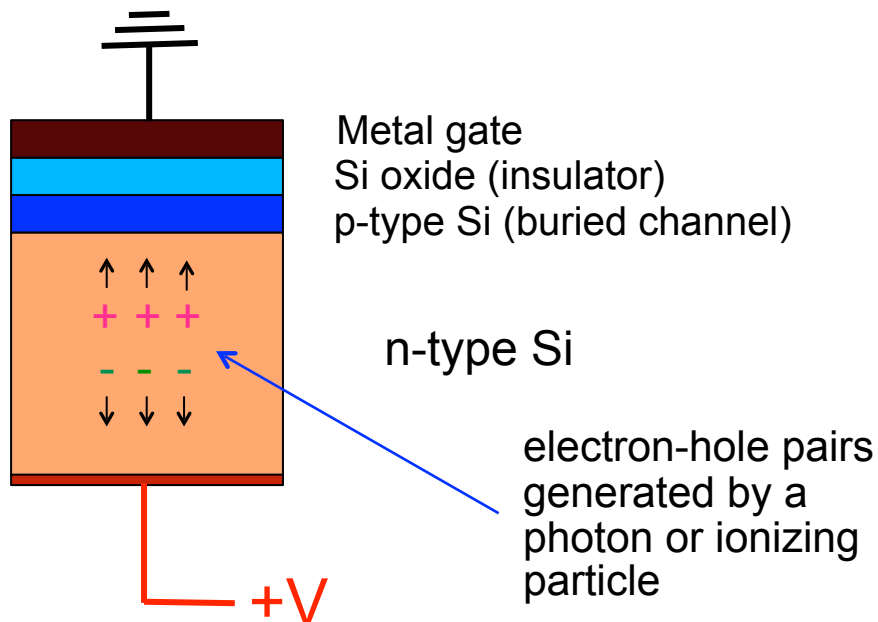


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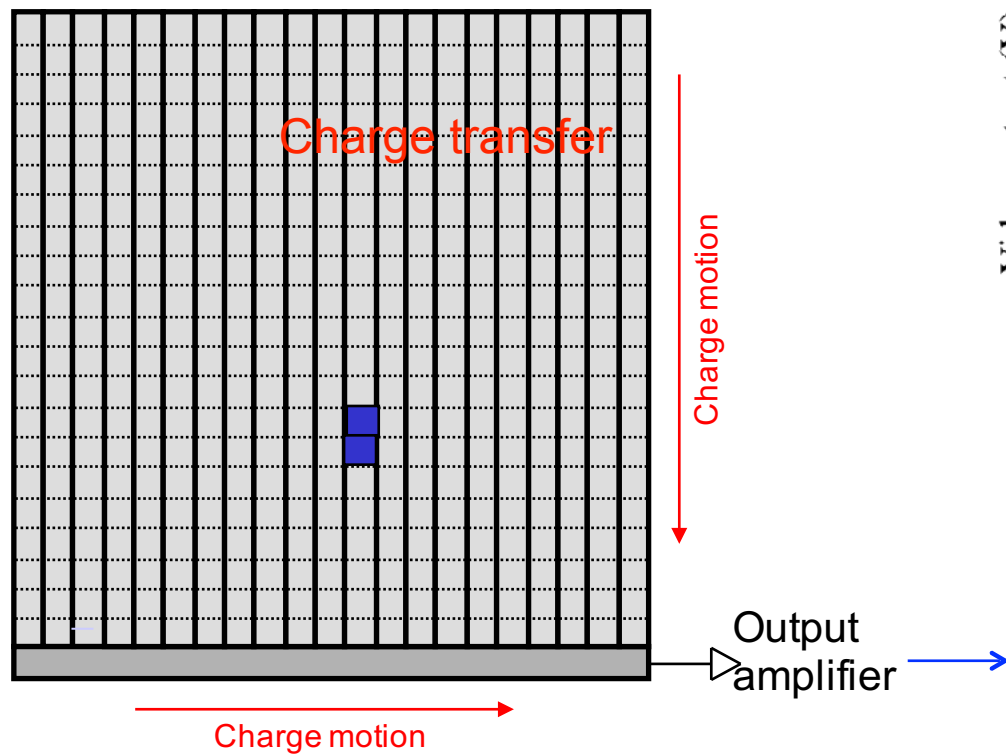
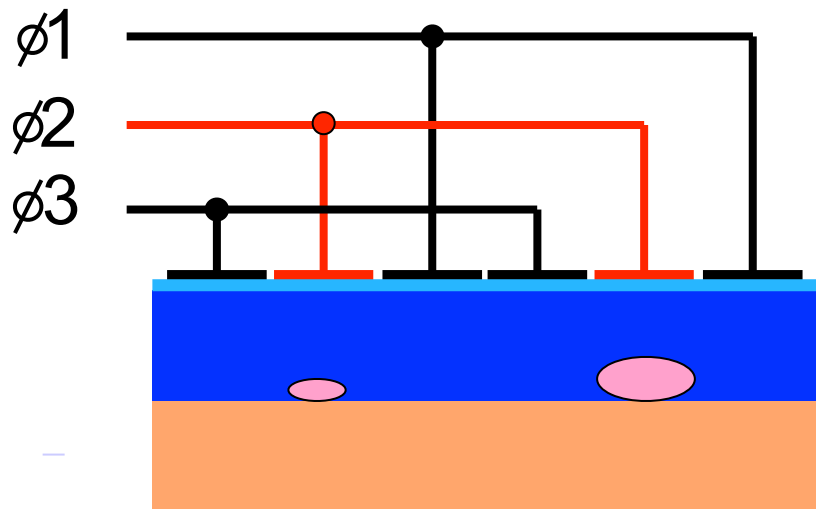


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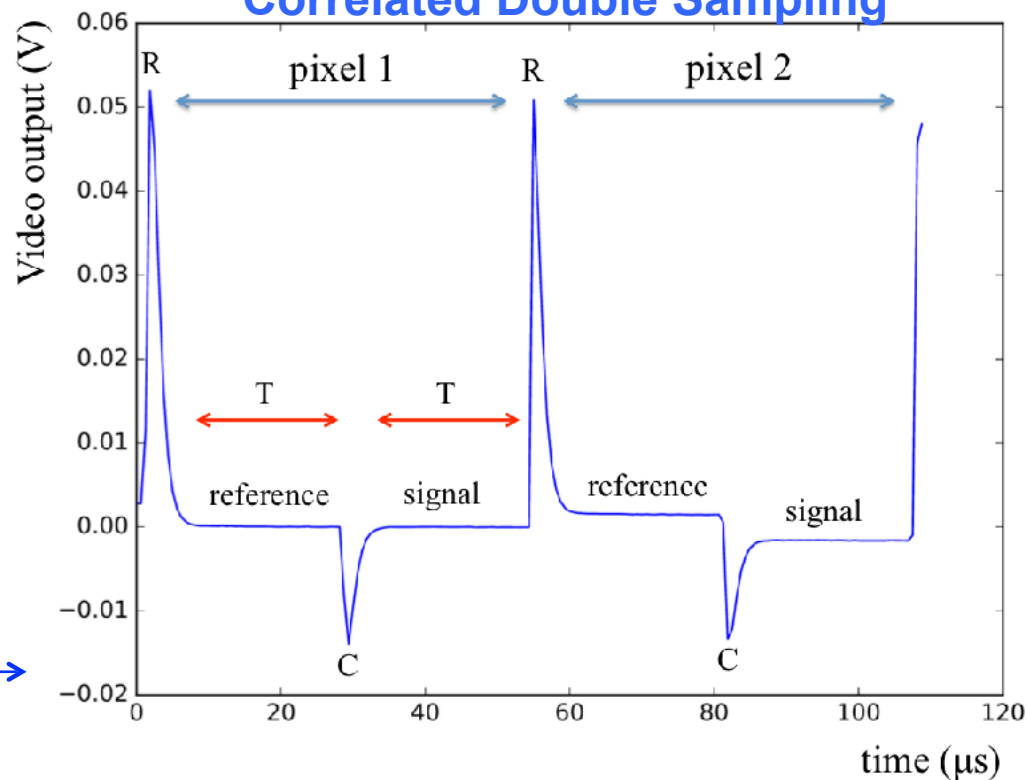


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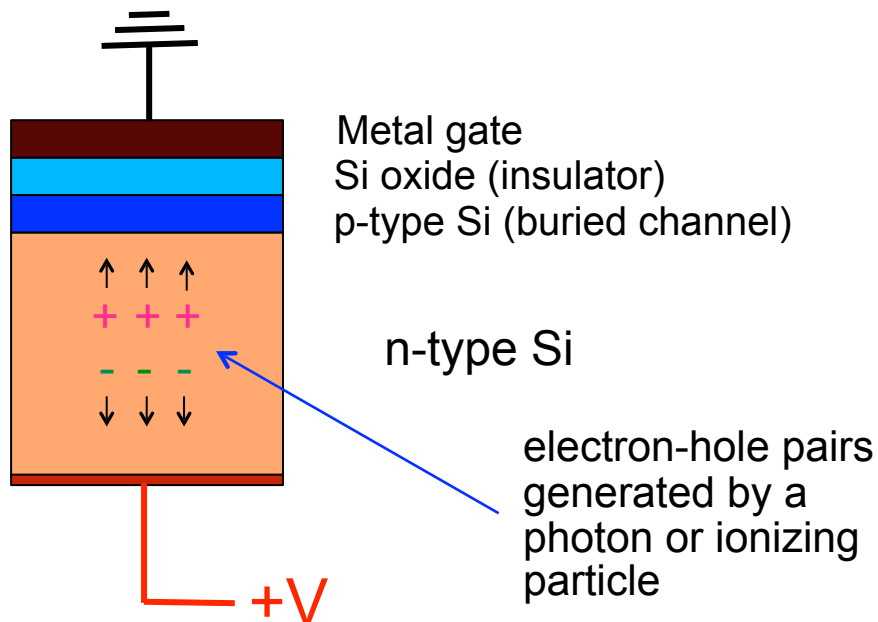
## Charge transfer ("Clocks")



## Correlated Double Sampling

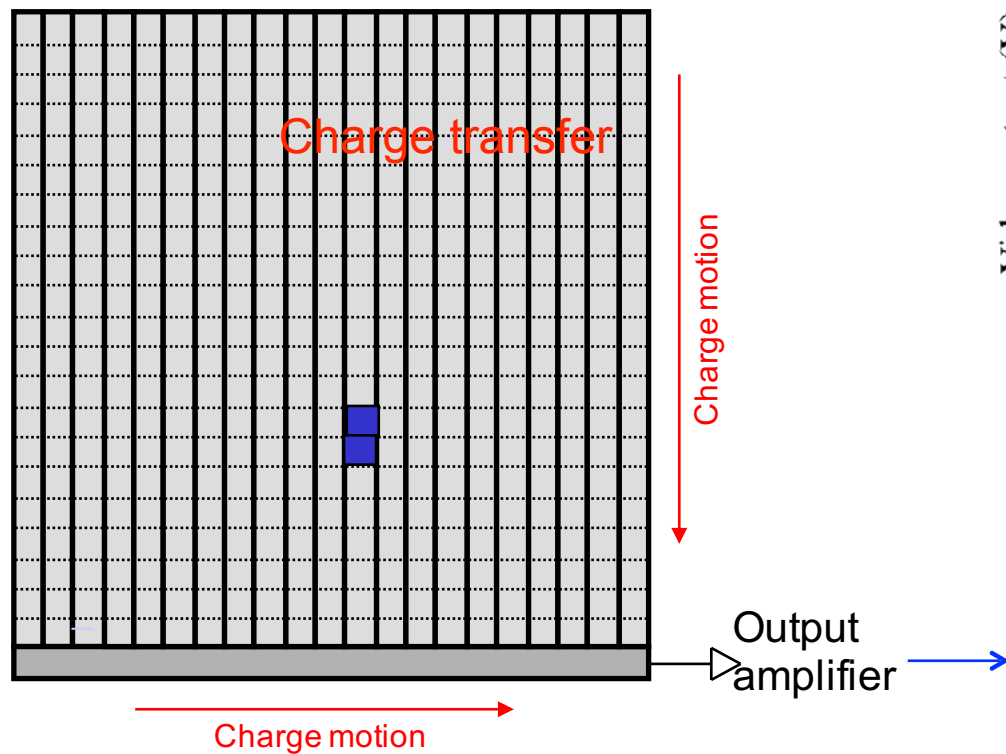
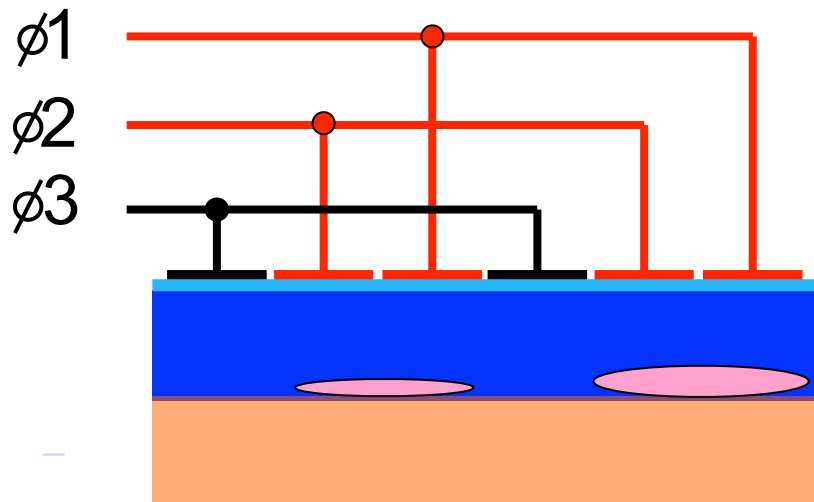


# Metal-Oxide-Semiconductor capacitor

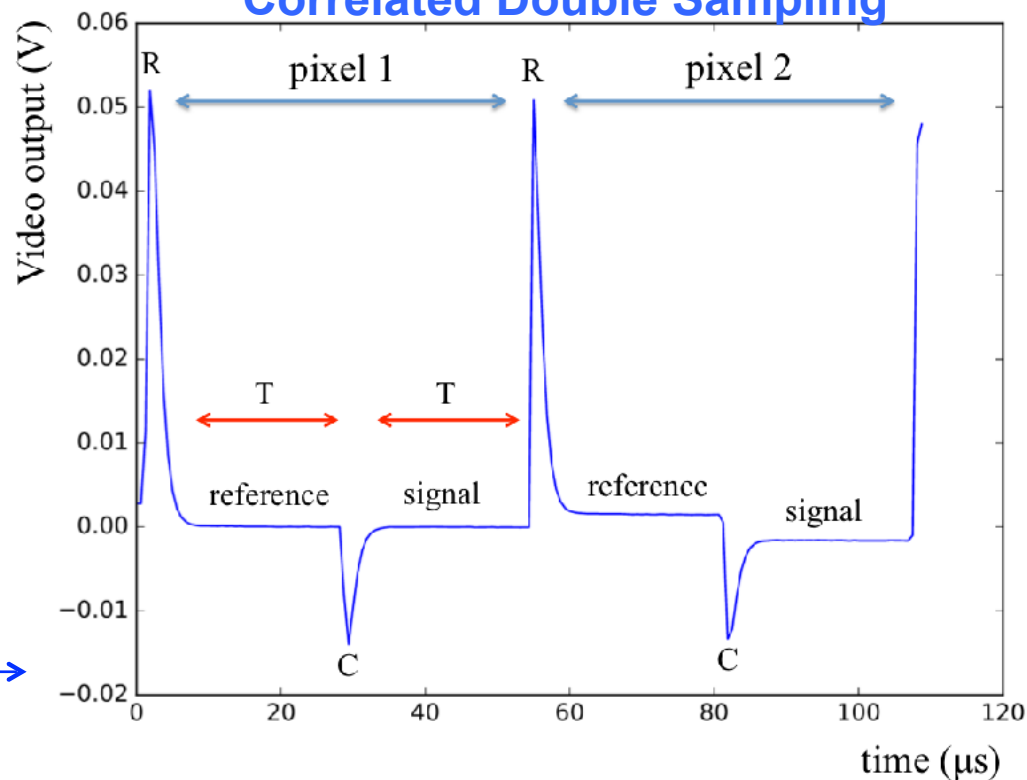


# Charge Coupled Device

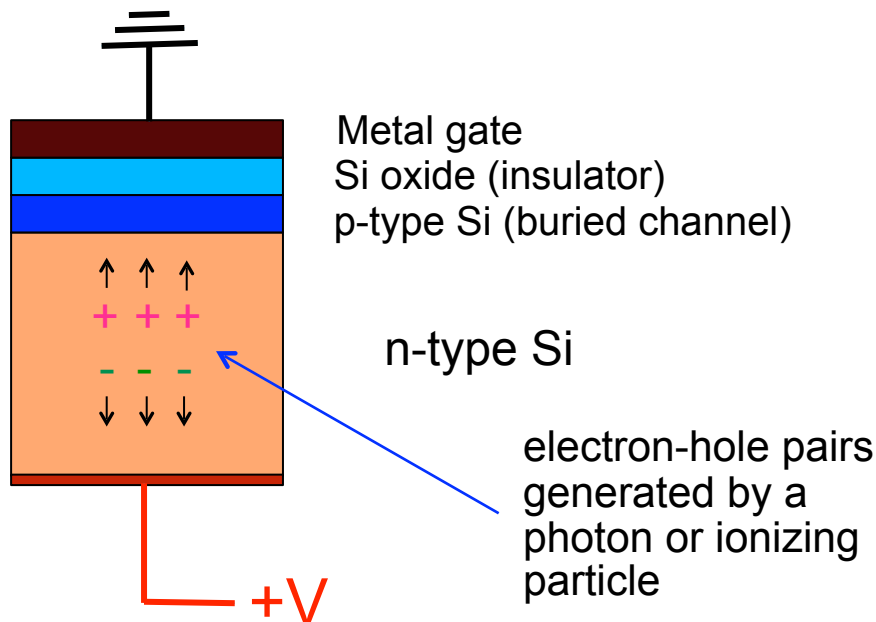
## Charge transfer ("Clocks")



## Correlated Double Sampling

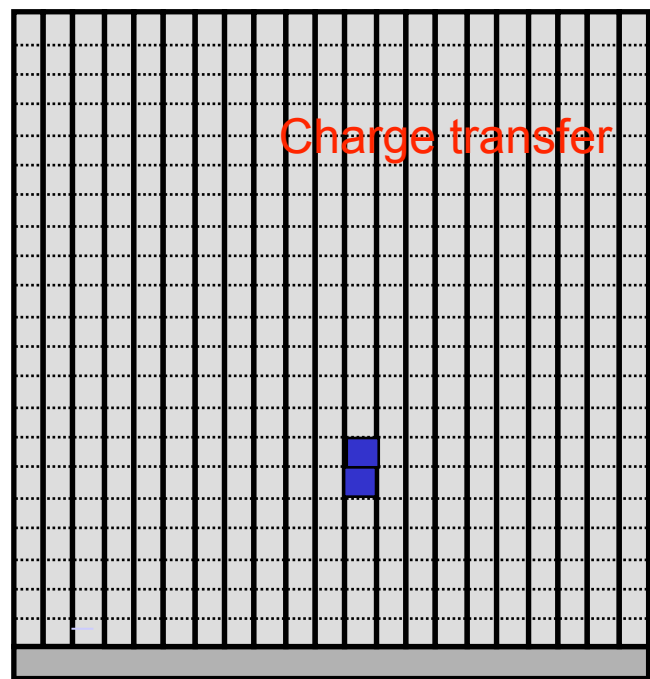
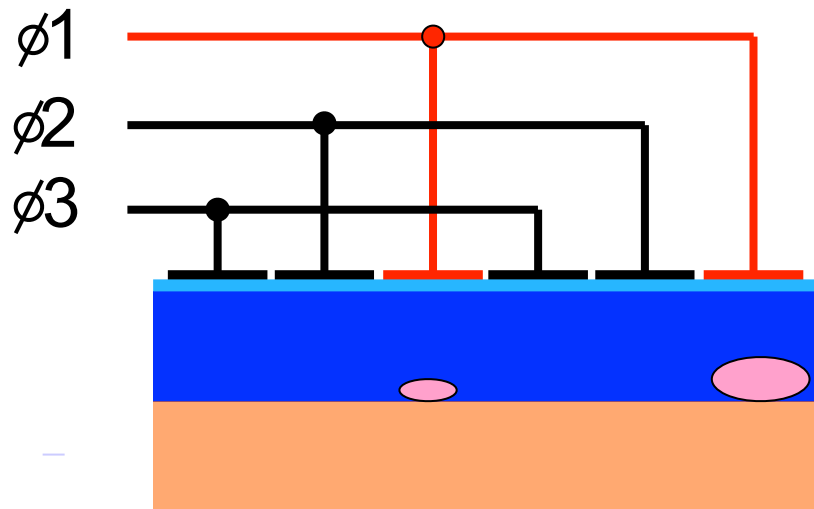


# Metal-Oxide-Semiconductor capacitor



# Charge Coupled Device

## Charge transfer ("Clocks")



Charge motion

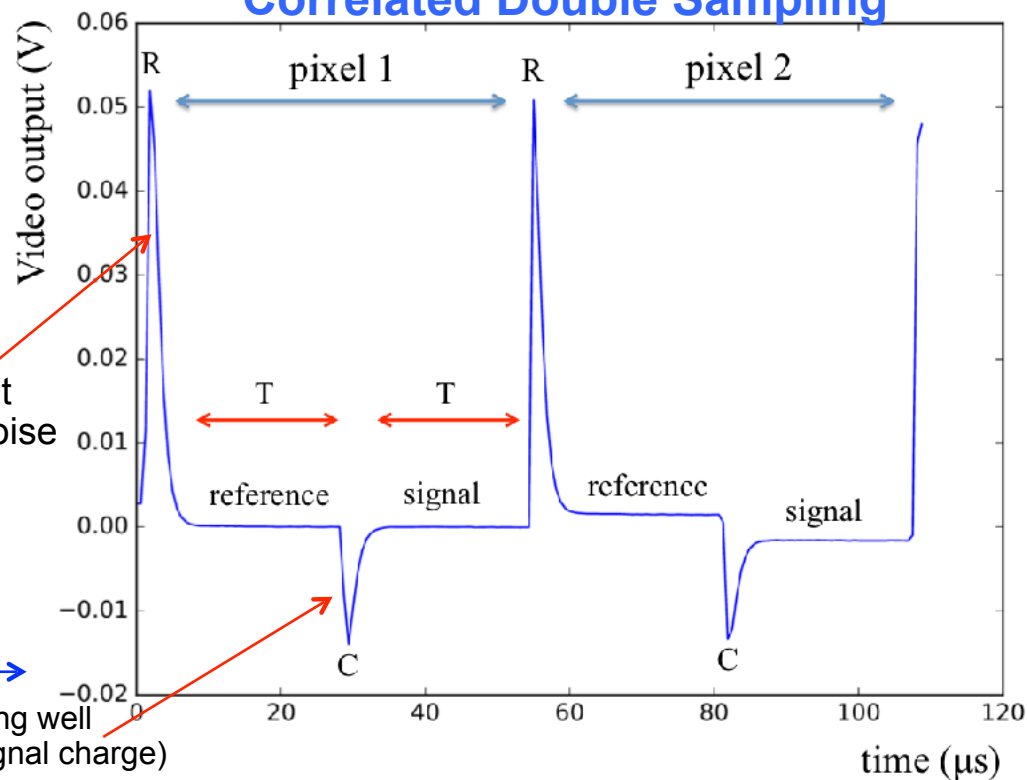
Amplifier reset (introduces noise charge)

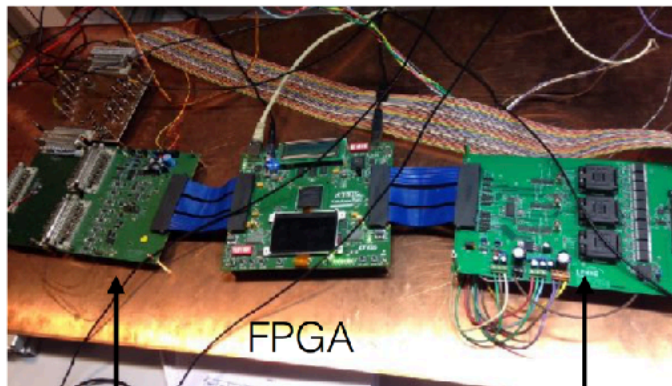
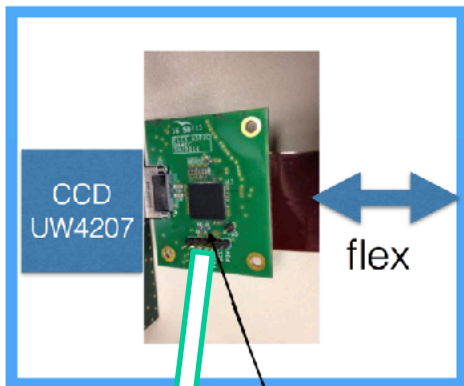
Output amplifier

Summing well (add signal charge)

Charge motion

## Correlated Double Sampling





# Electronics

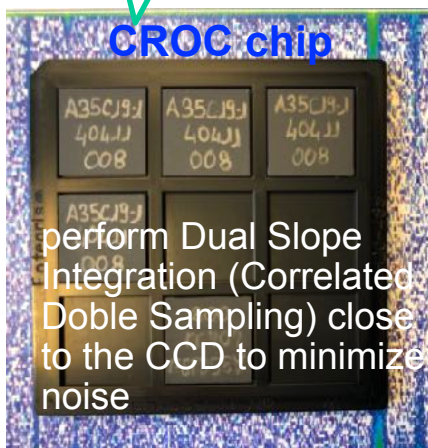
successful test of CCD Controller components (CABAC ASIC for clocks, ADC, ASPIC chip for CDS)

ASPIC (LSST)

BEB3 (ADC)

3CABAC board (CCD Clocks)

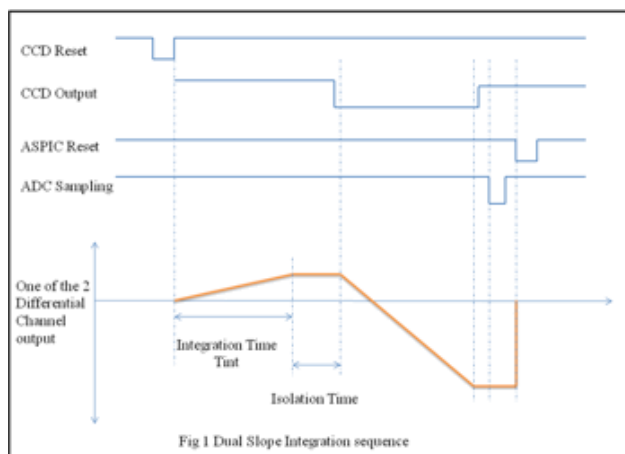
CROC chip



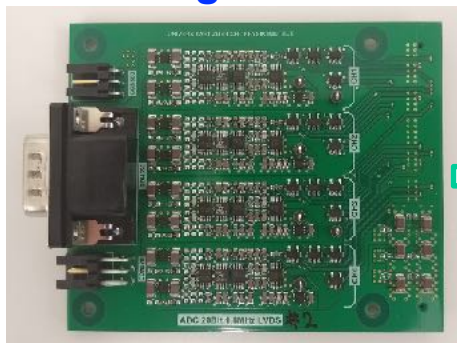
perform Dual Slope Integration (Correlated Double Sampling) close to the CCD to minimize noise

now integrated in a single controller board, one CCD per board

delivered, under test

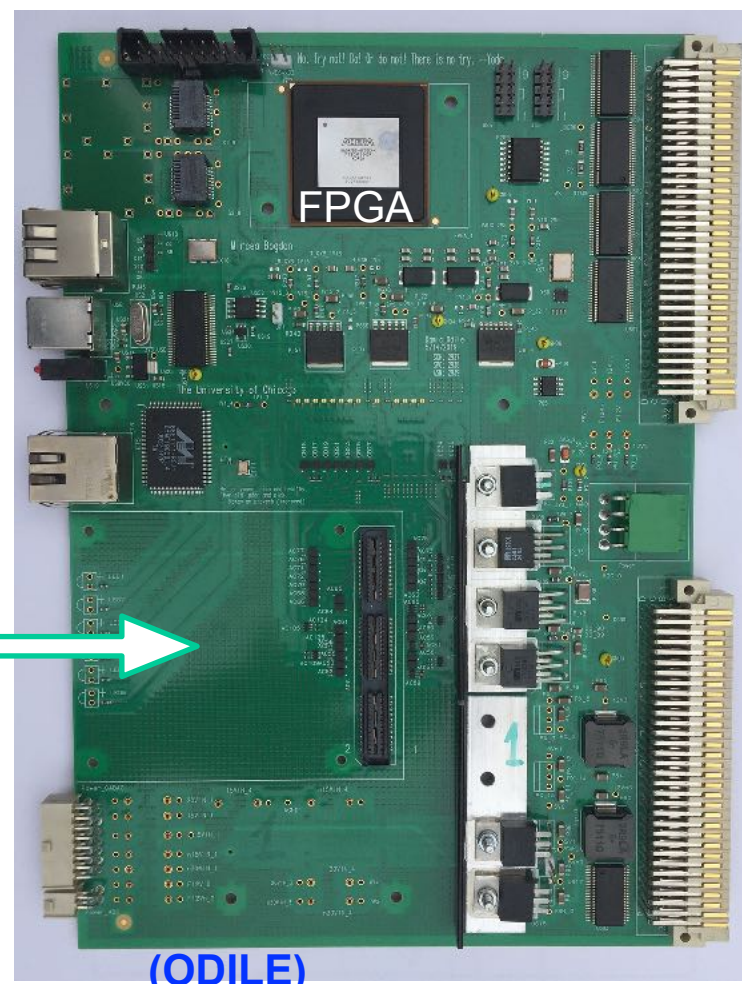


ADC daughter board



Two ADC being evaluated  
20 bit 1.6 MHz  
18 bit 15 MHz

CCD Controller Mother Board



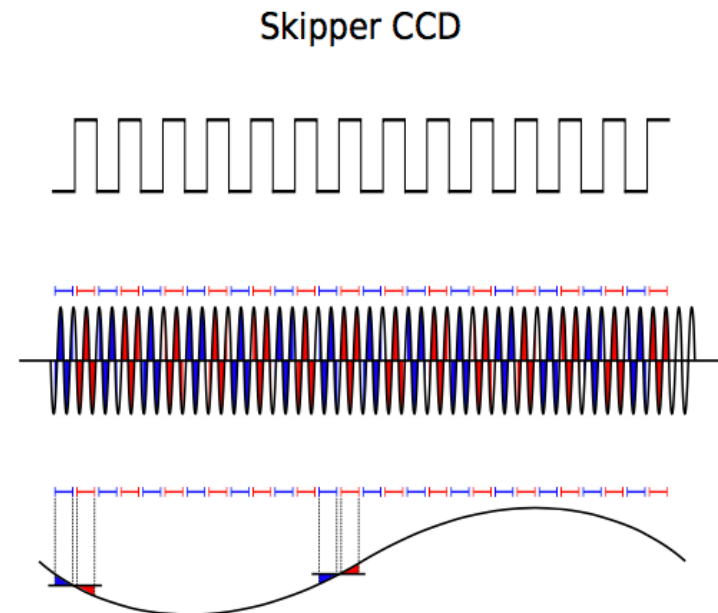
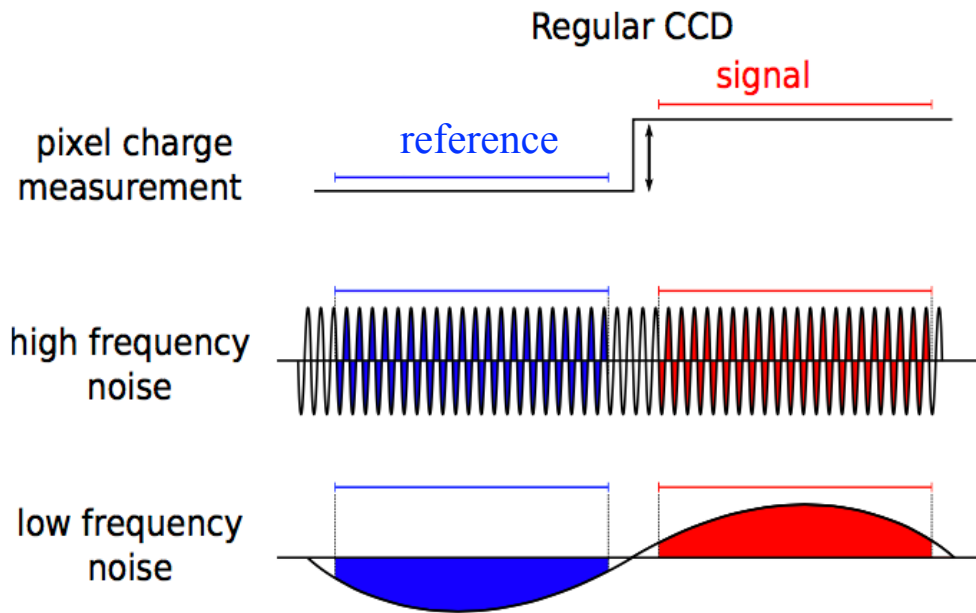
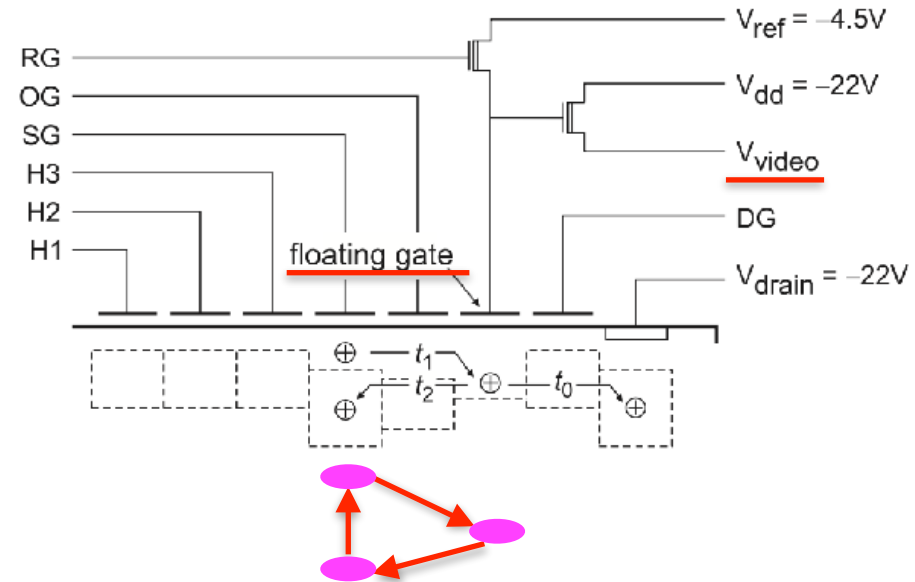
(ODILE)

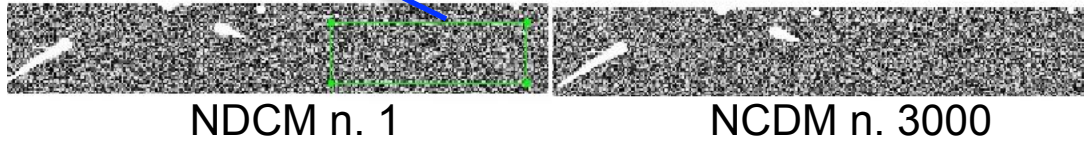
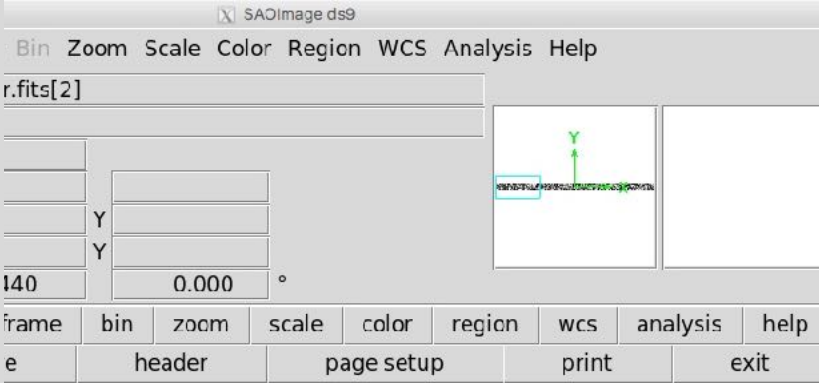
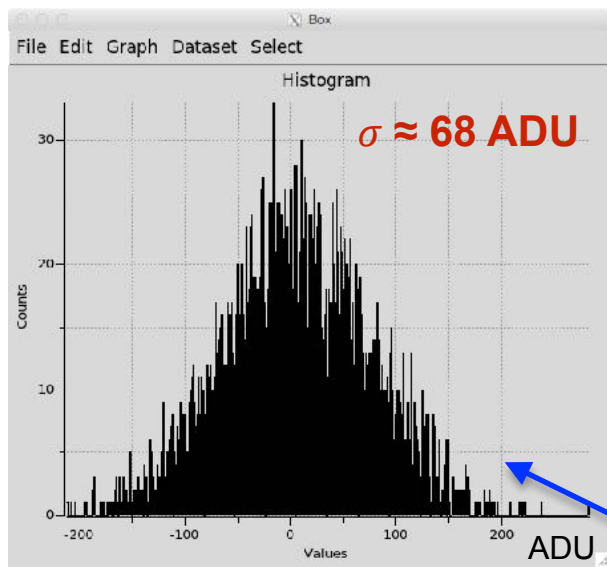
# Skipper CCD readout

Noise dominated by the  $1/f$  low frequency noise of the output amplifier

**Non-destructive** charge measurement!  
(NDCM)

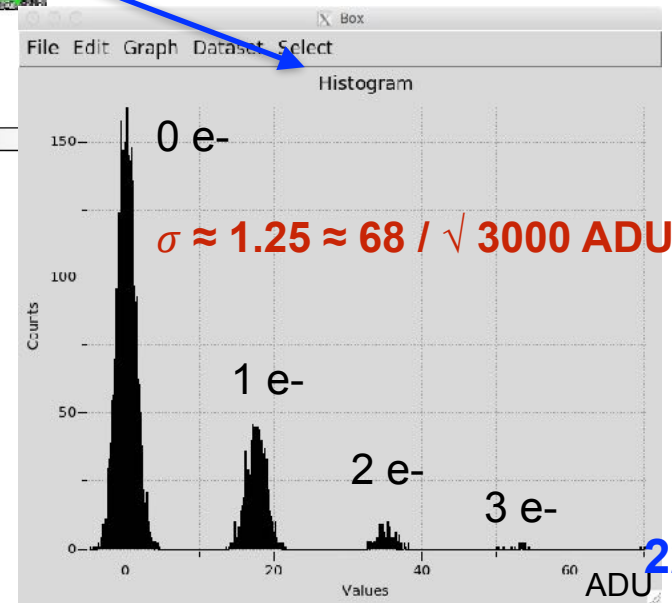
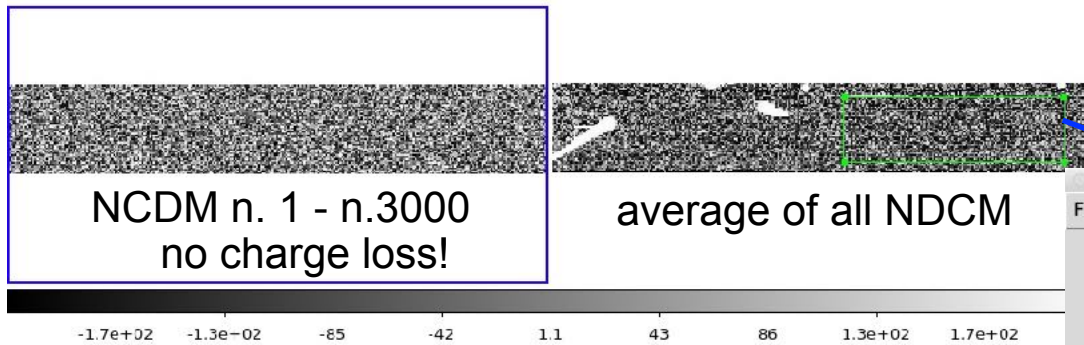
Measure the charge fast (kill  $1/f$  noise) and  $N$  times (noise  $\approx 1/\sqrt{N}$ )





**DAMIC-M prototype  
skipper CCDs**

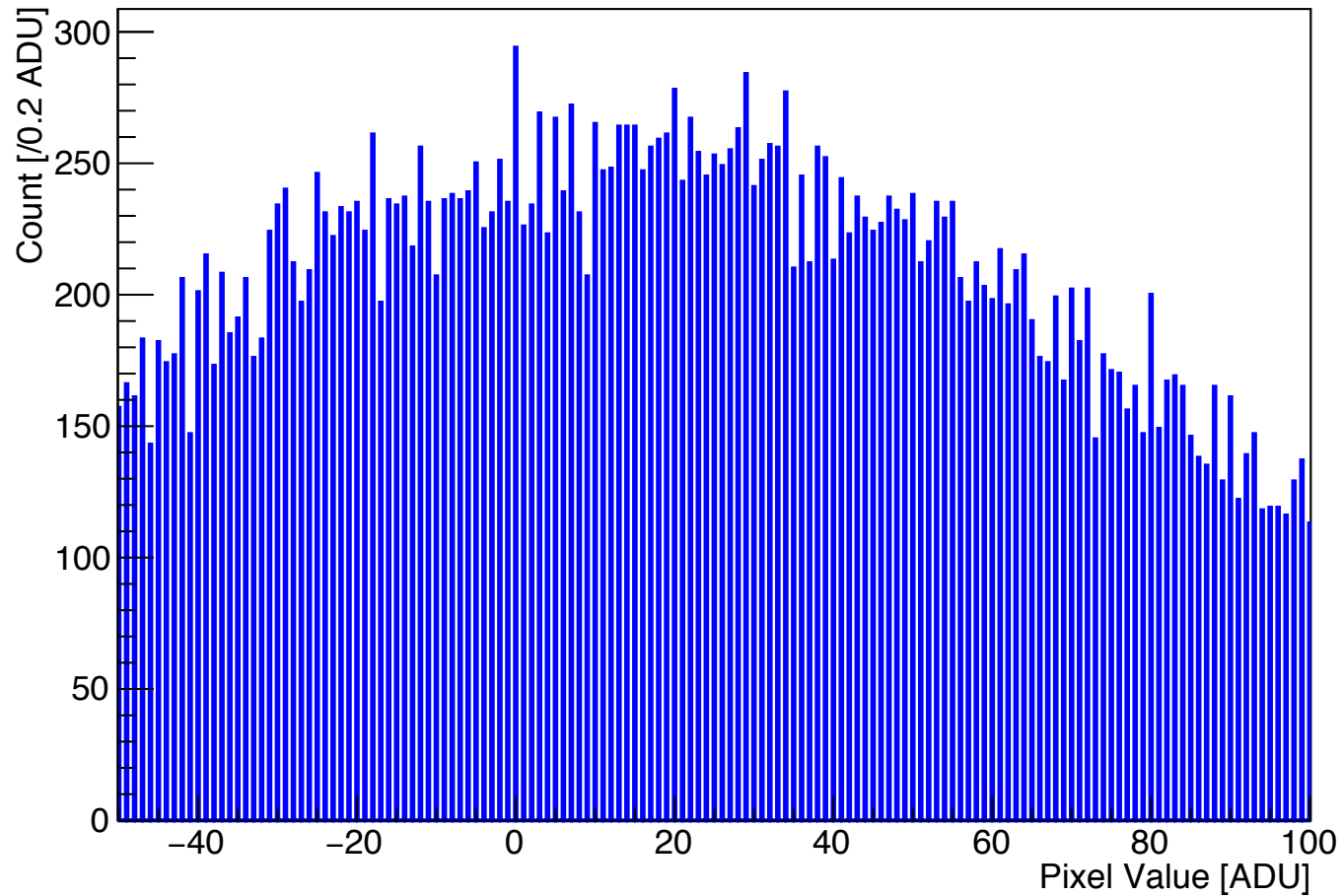
**RAW DATA!**



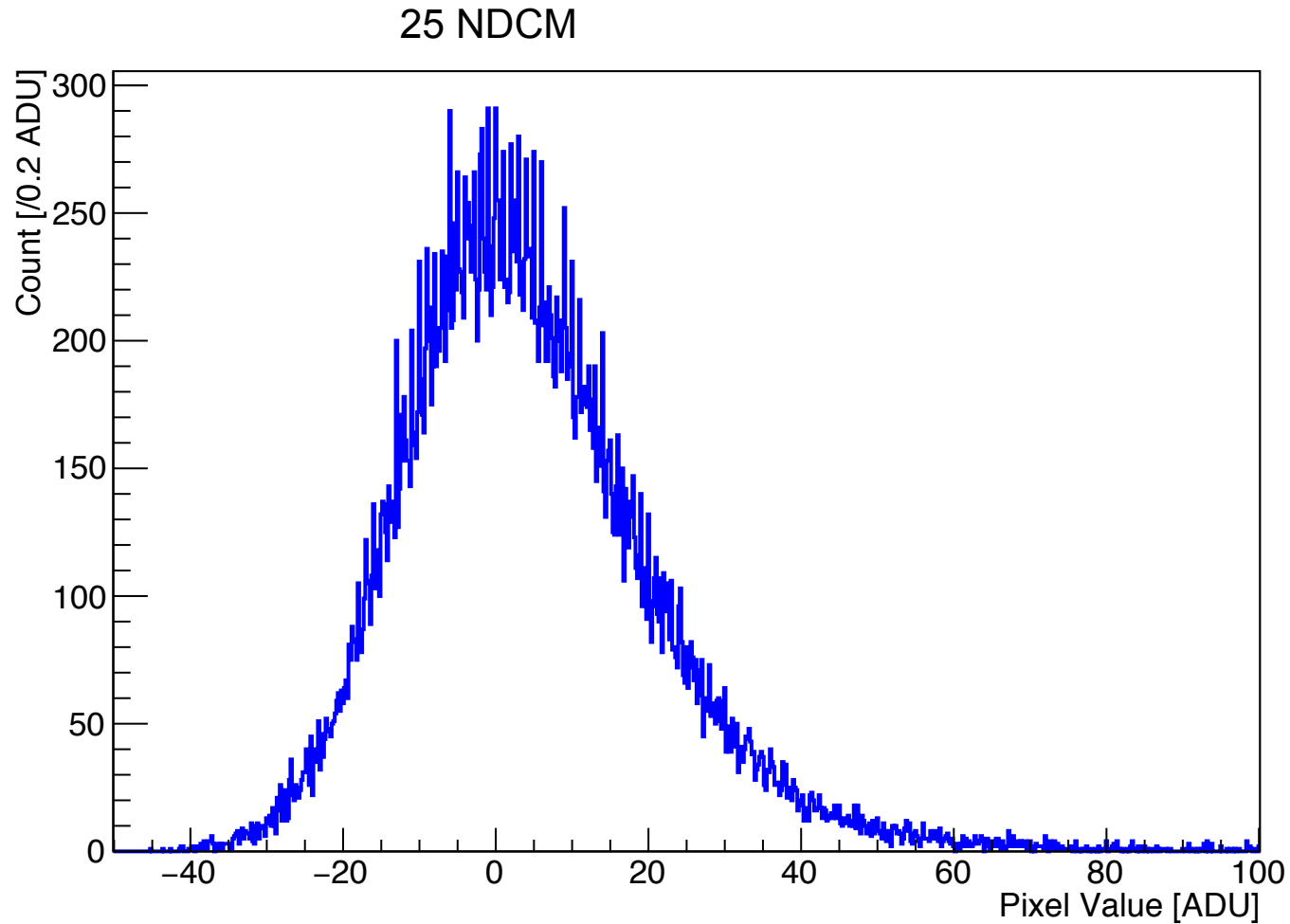
**Single electron  
charge resolution**

# DAMIC-M Skipper charge resolution

1 Non Destructive Charge Measurement

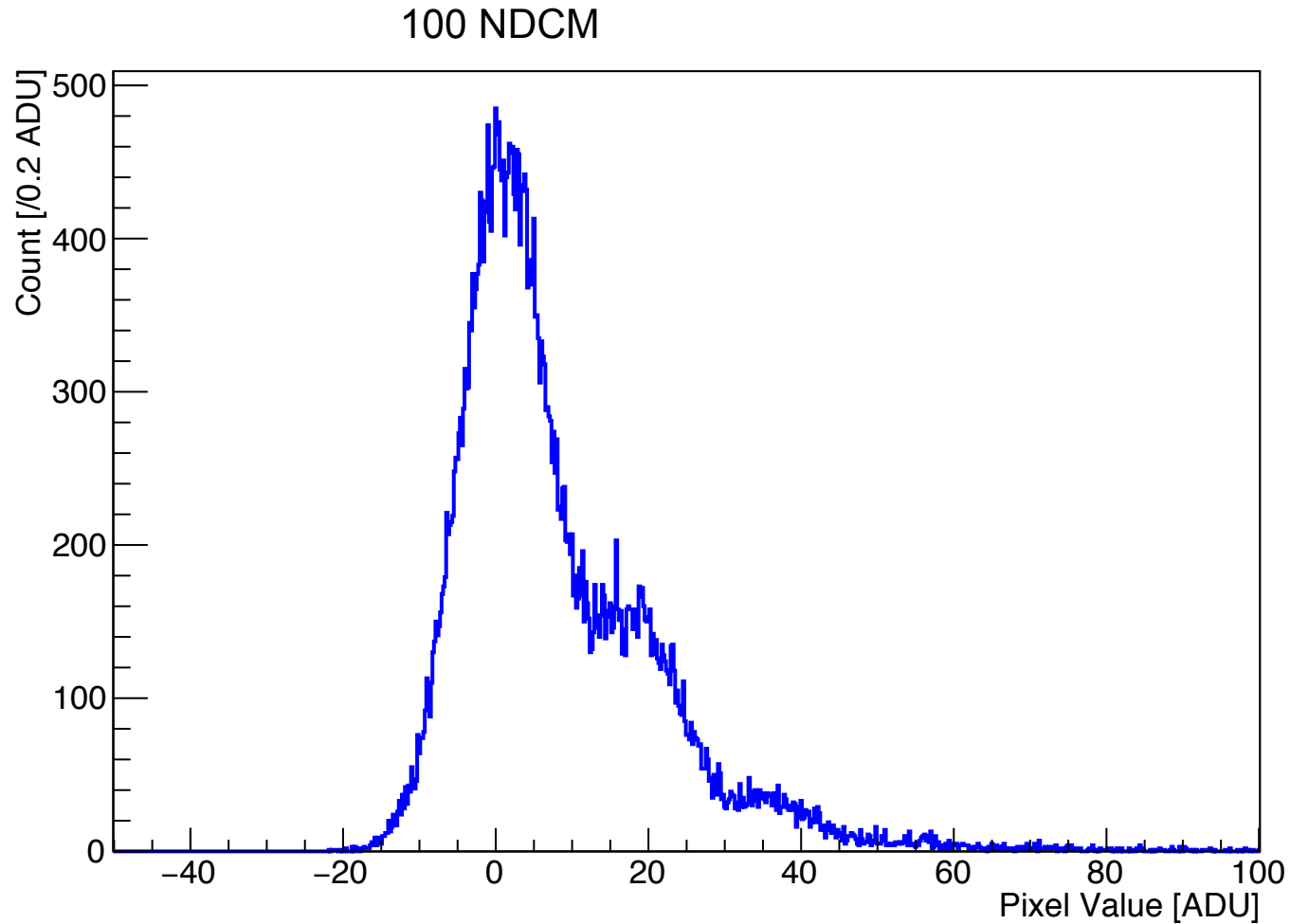


# DAMIC-M Skipper charge resolution

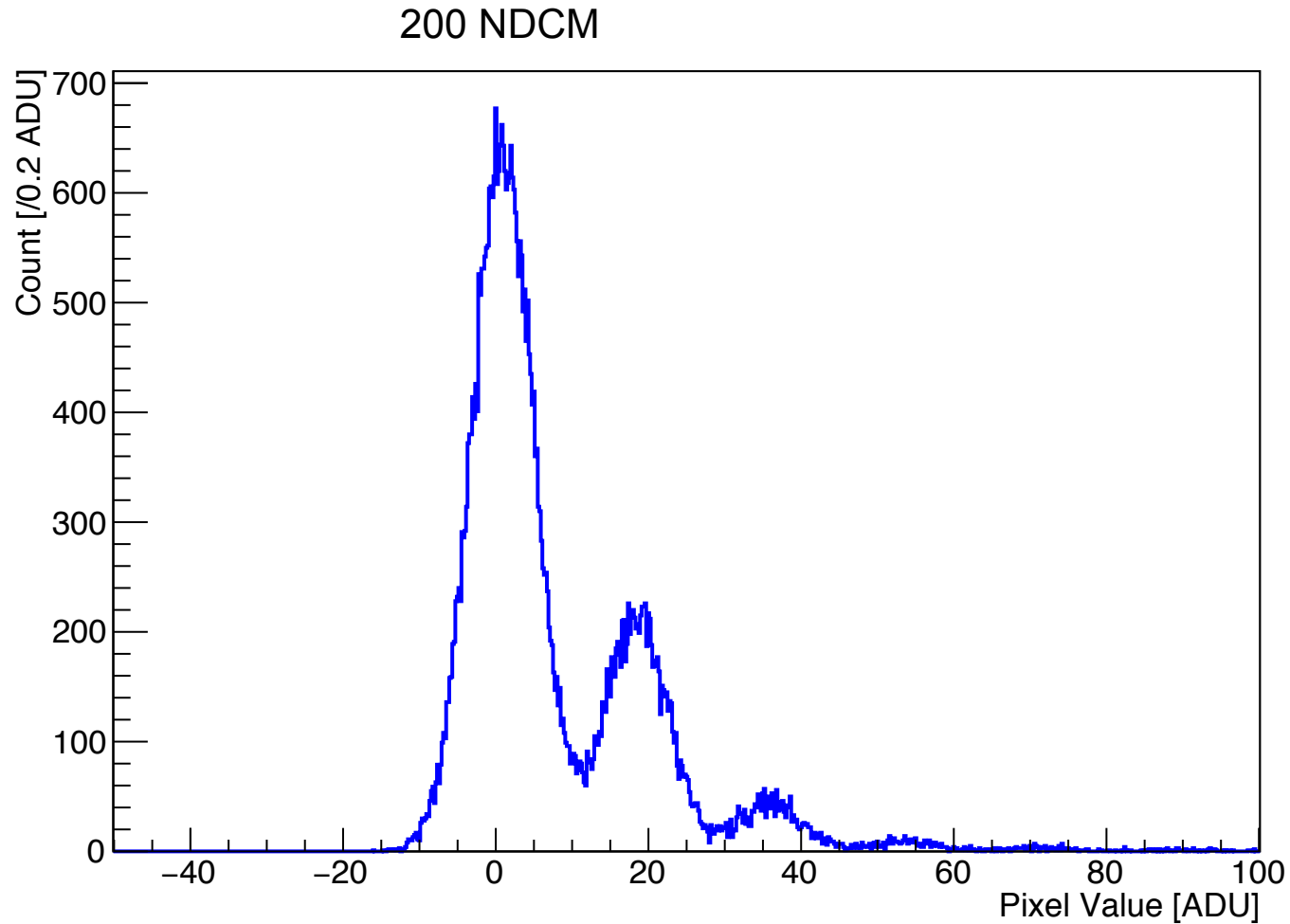




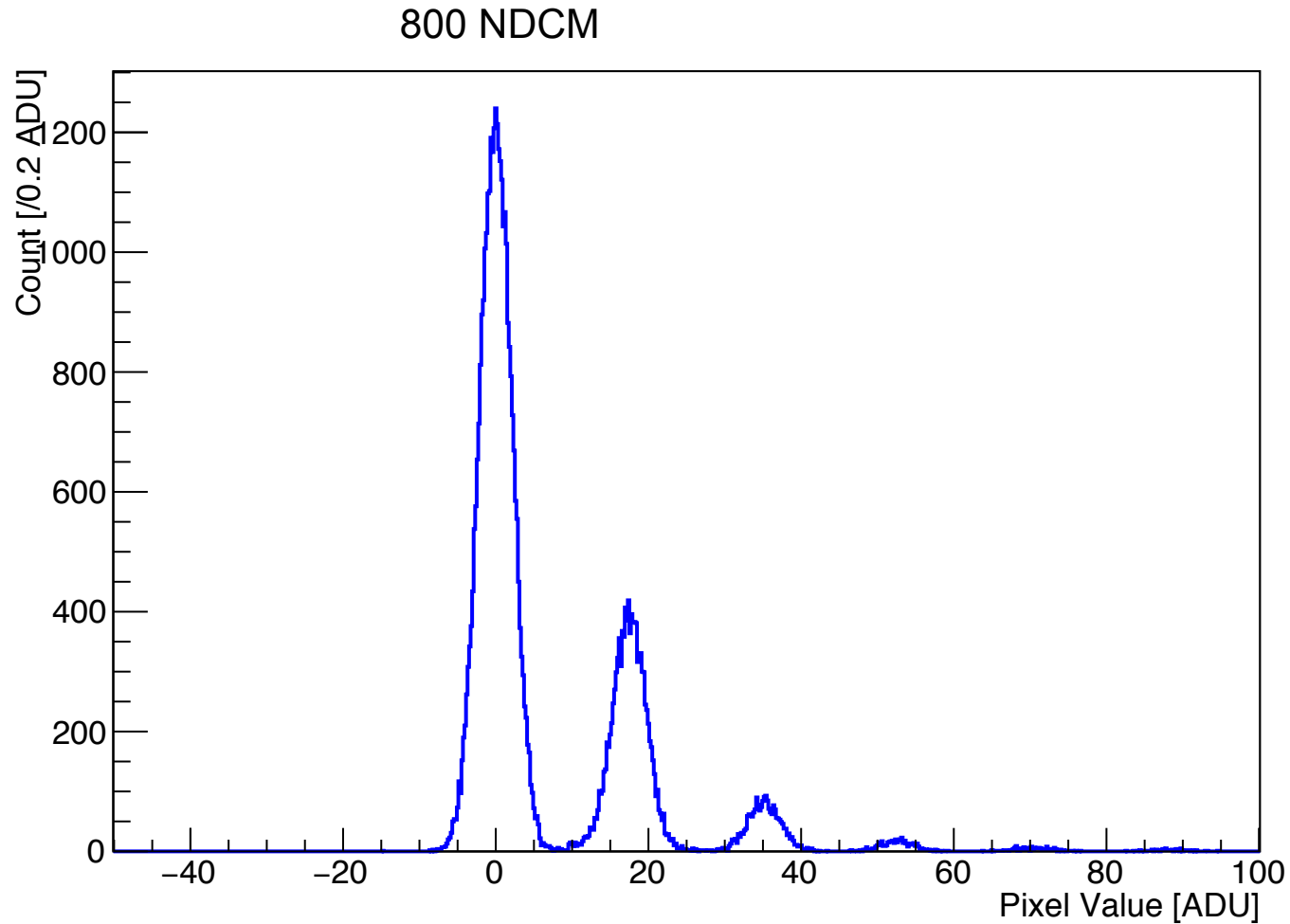
# DAMIC-M Skipper charge resolution



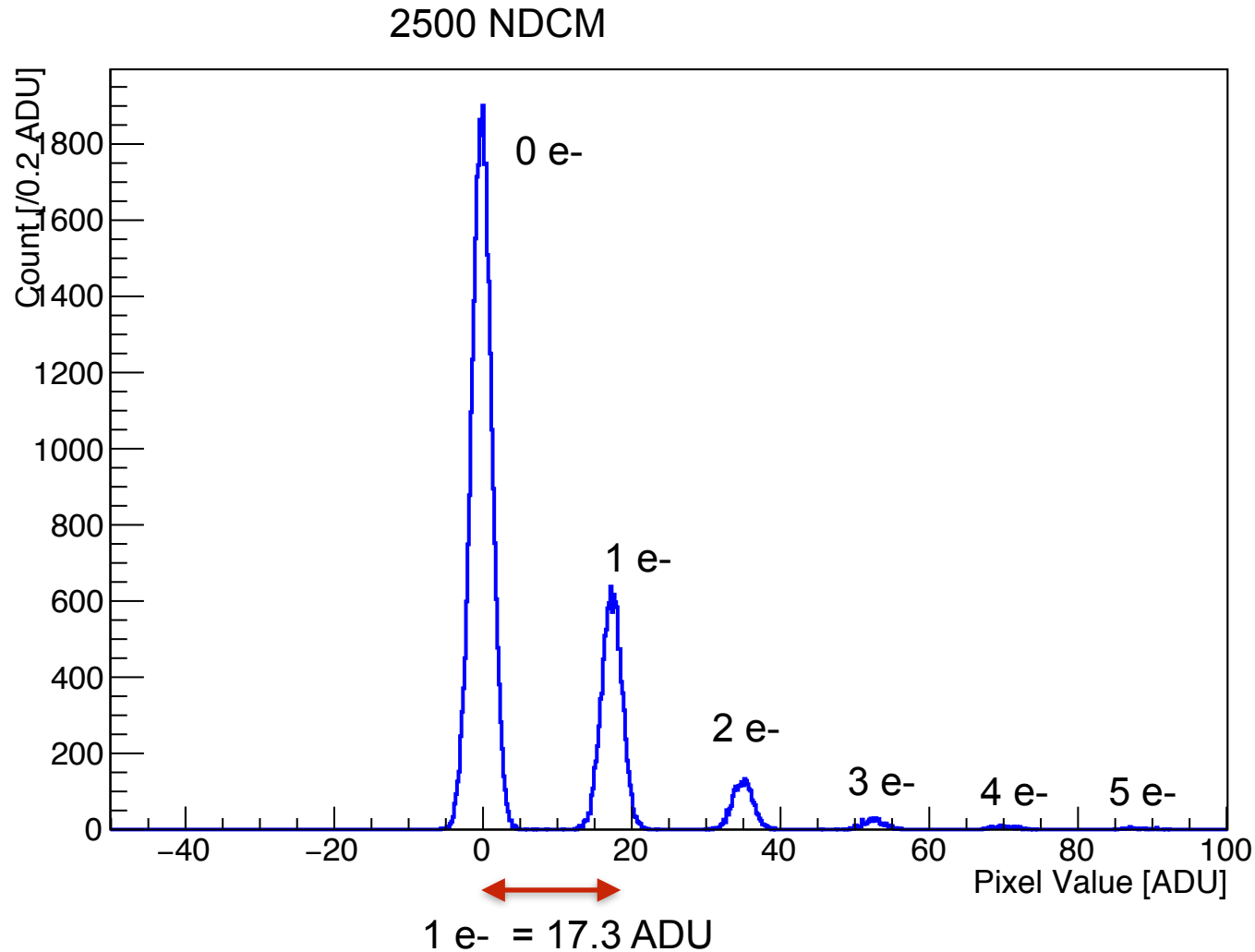
# DAMIC-M Skipper charge resolution



# DAMIC-M Skipper charge resolution

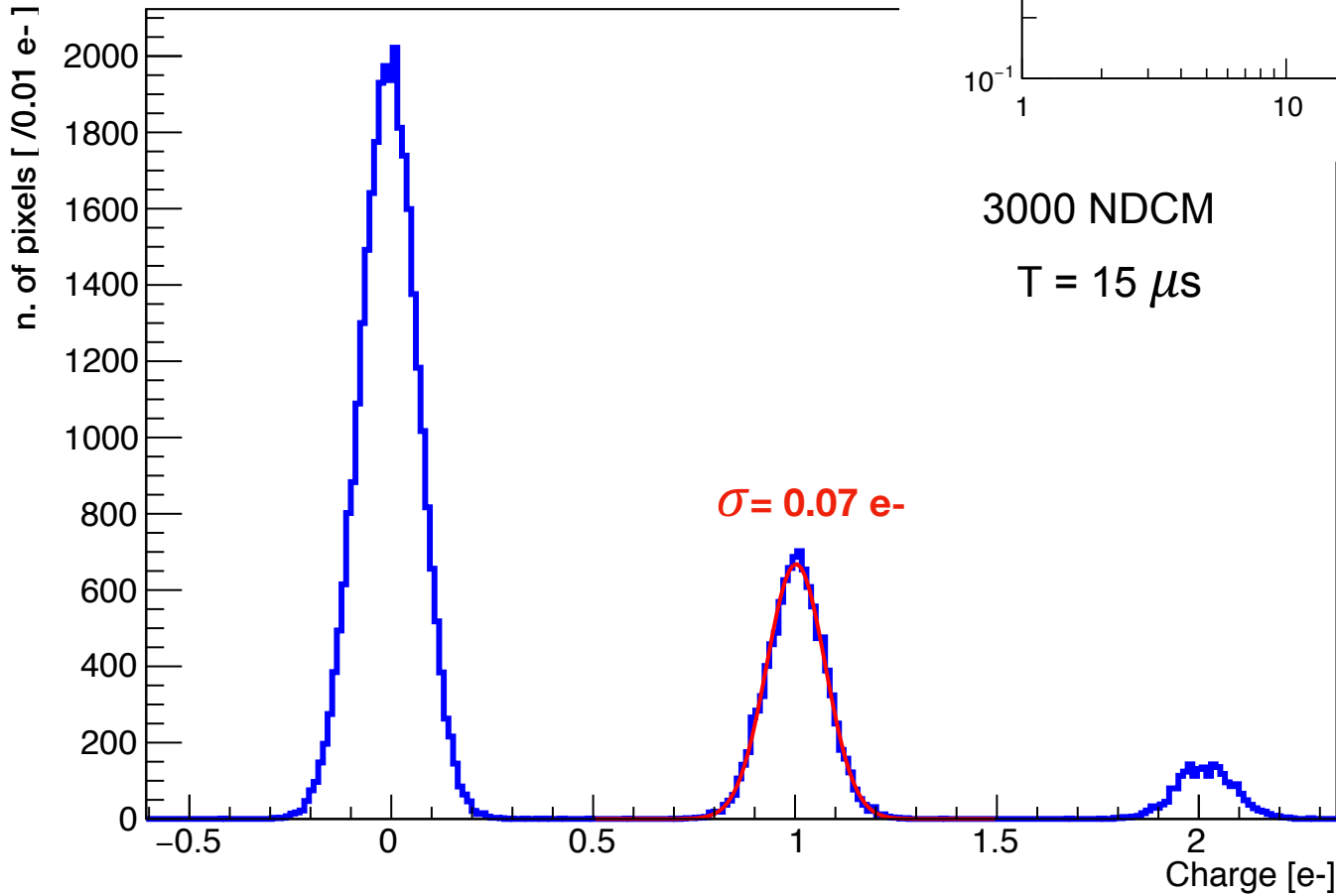
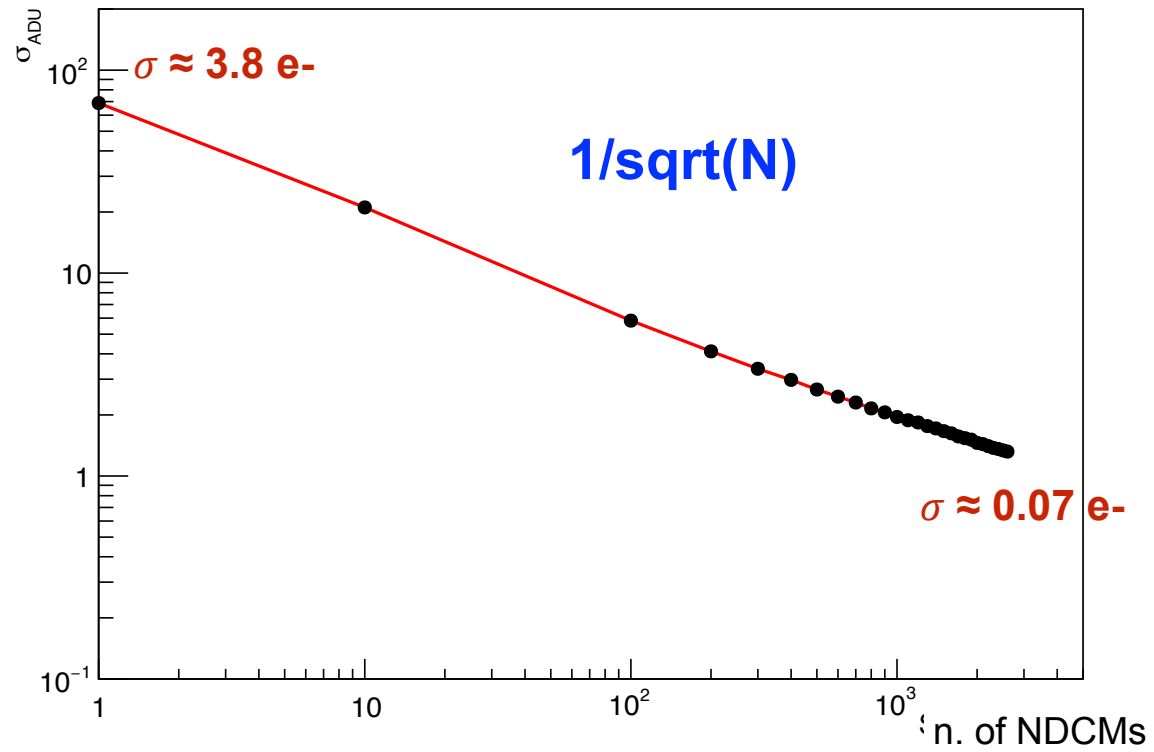


# DAMIC-M Skipper charge resolution

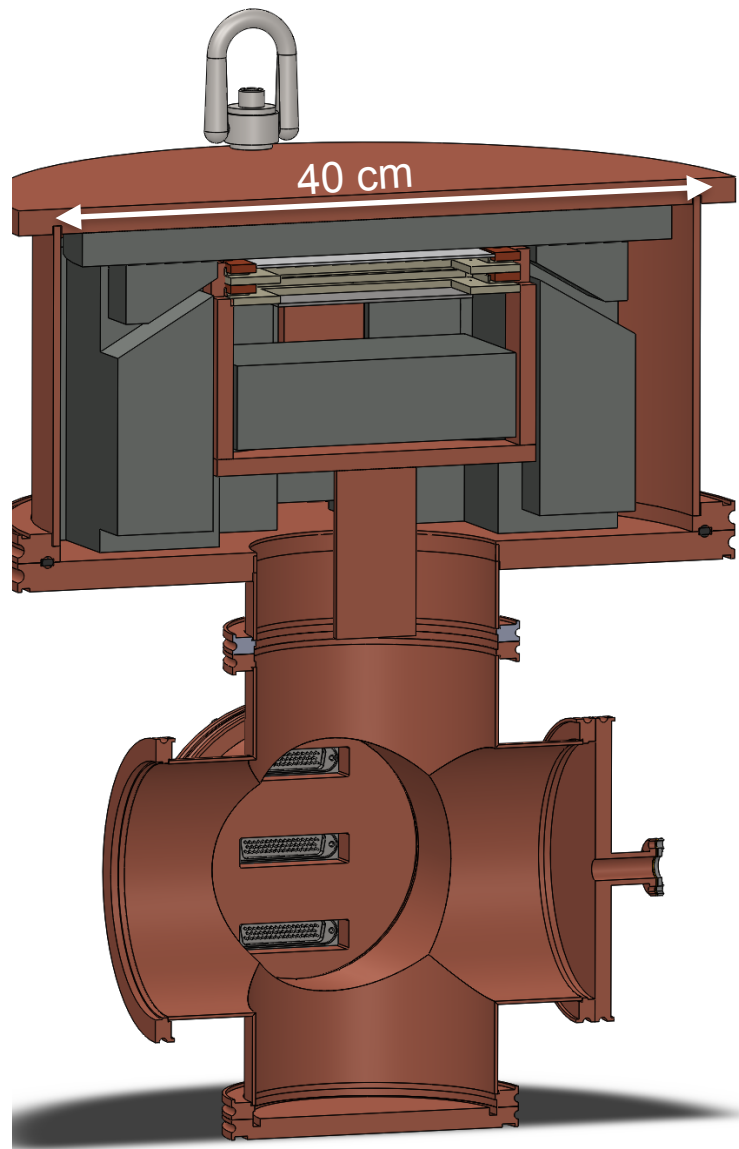


direct calibration of ADU to charge  
(cross checked with  $^{57}\text{Co}$  source)

Single electron resolution  
obtained for a wide range of  
integration times ( $T = 4 - 20 \mu\text{s}$ )  
allowing optimization with respect  
to electronics noise



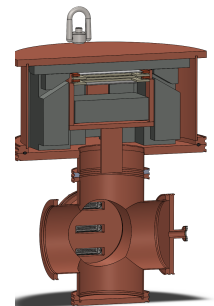
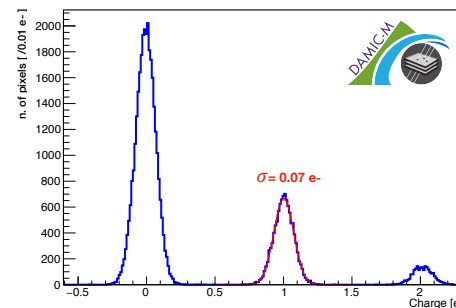
# Low Background Chamber



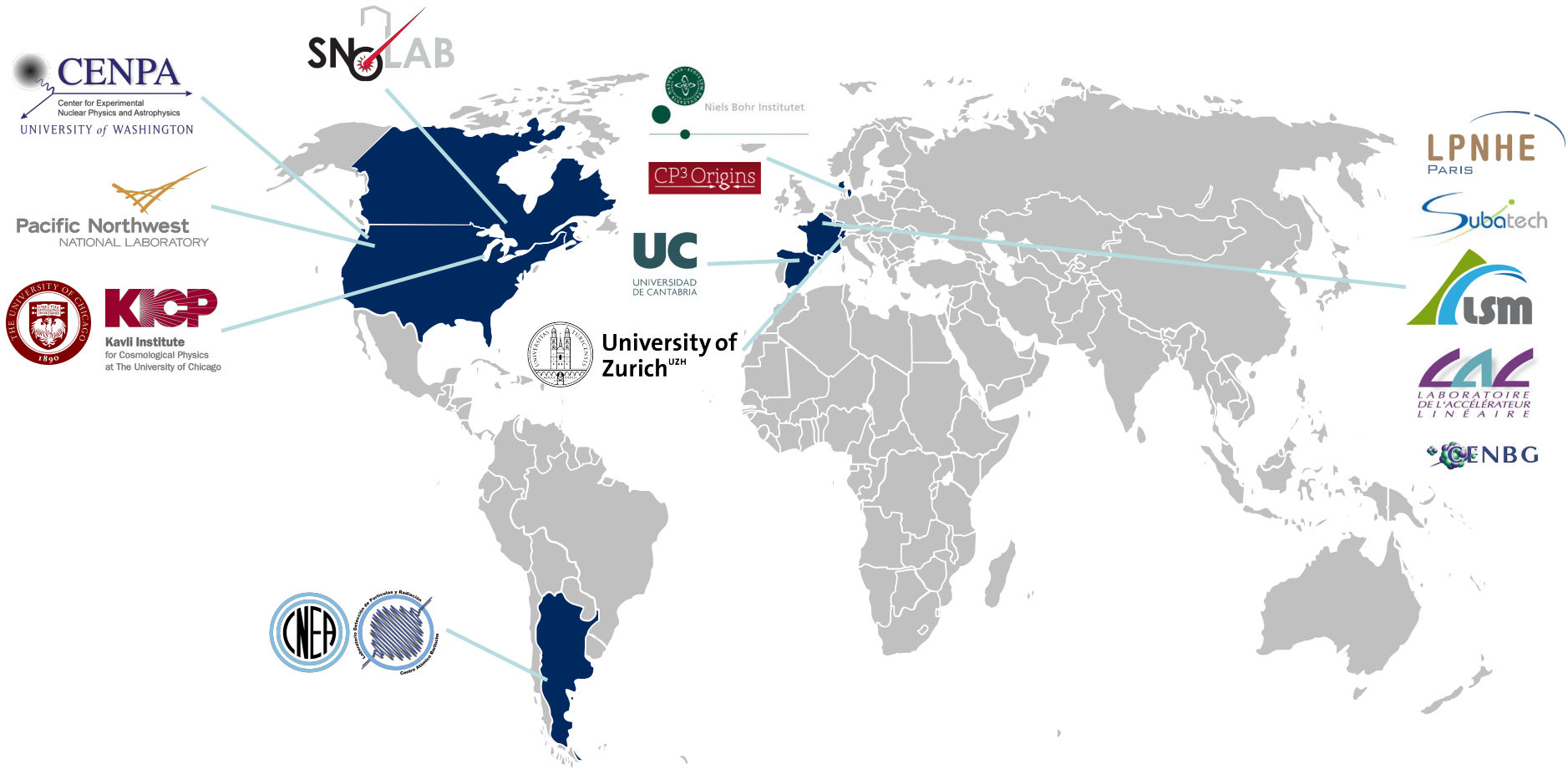
- A low-background chamber (background level  $\approx$  dru) is in preparation
- Main objectives:
  - characterization of DAMIC-M CCDs in low-bkg environment: dark current;  $^{32}\text{Si}$  rate;  $^{210}\text{Pb}$  surface bkg; CCD packaging
  - first science results with a few CCDs
- Installation at LSM beginning of 2020

# Outlook

- DAMIC-M is pushing to a kg-size detector the high-resistivity, fully-depleted CCD technology pioneered at SNOLAB
- The experiment is in its design phase. Progress on all aspects: detector design, electronics, low-background
- Major milestones accomplished: silicon ingot production; demonstration of single electron resolution with large-size, thick CCDs implementing skipper design
- We are moving fast. Before the end of this year, installation of DAMIC-M clean room at LSM and CCD pre-production. CCD production scheduled for next year.
- A low-background chamber will be installed at the LSM beginning of 2020 to characterize DAMIC-M skipper CCDs underground in a low background environment. Early science results with a few CCDs are foreseen.



# DAMIC-M Collaboration





# The Laboratoire Souterrain de Modane

